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DMS-SA30

Rev.1.2

Intel Skylake-S

CPU:

Intel SKL-S CPU (LGA1151)
Max. TDP: 35W

System Chipset:

Intel 100 series
Q170/H110

Main Memory:

DDR4-1866/2133 SO-DIMM x2 (1DPC, Max:32GB)

On Board Chip:

HDMI to LVDS - TSUMU58DC2-1
DP to VGA - CH7517A
Super I/O - NCT6106D
Audio - Realtek Codec ALC898 + Amplifier TPA2008D2
LAN - Intel Jacksonville i219LM(Q170) / V(H110)
BIOS - SPI Flash ROM 128MB(Q170) / 64MB(H110)
TPM 2.0/1.2 - SLB9665/9660 (Q170 Sku)
GL850G - USB2.0 HUB (H110 Sku)

VRM Controller:

IMVP8-ISL95855(VCCP/VCCGT/VCCSA)
ISL8016(VCCIO)
NCP1589L(VCC_DDR) + UP1727(VPP_DDR)
NCP1589L(PCH_1VSB)
NCP1589A(+12VSB)
TPS40210DGQ(+24VSB)
TPS51125RGER(SYS_PWR)

Expansion Slots:

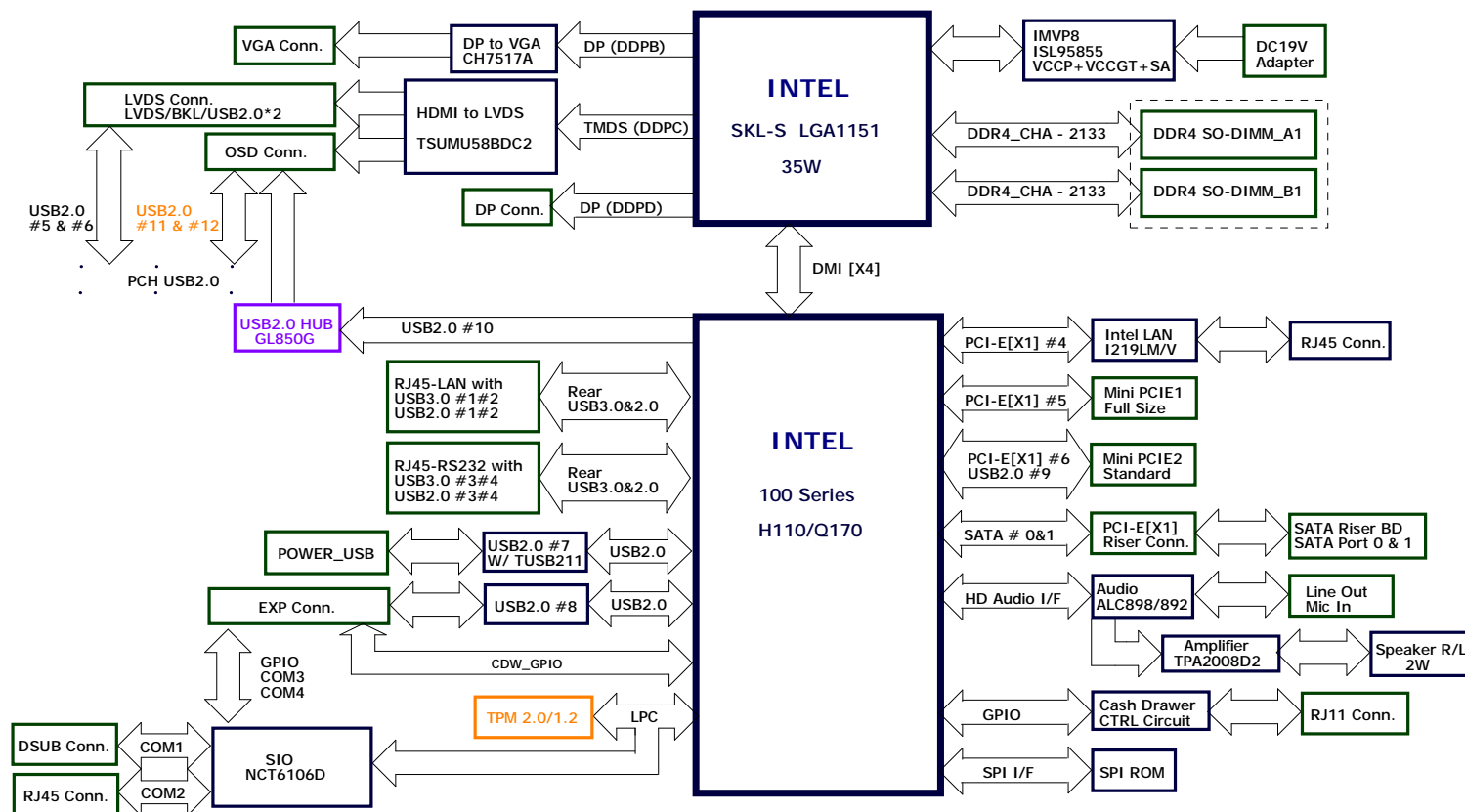
SATA Riser Connector (2* SATA ports)
Mini-PCIE *2
Expansion Board (RS232*2, USB*1 ...)

Others :

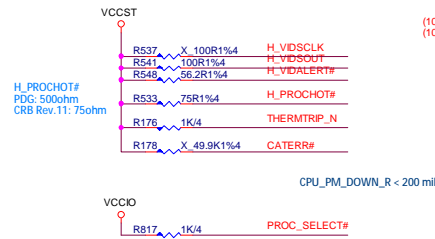
Cash Drawer
Power USB



Block Diagram

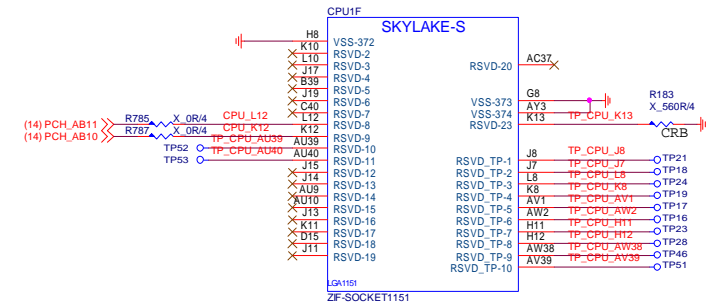
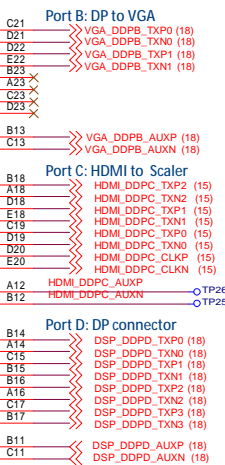
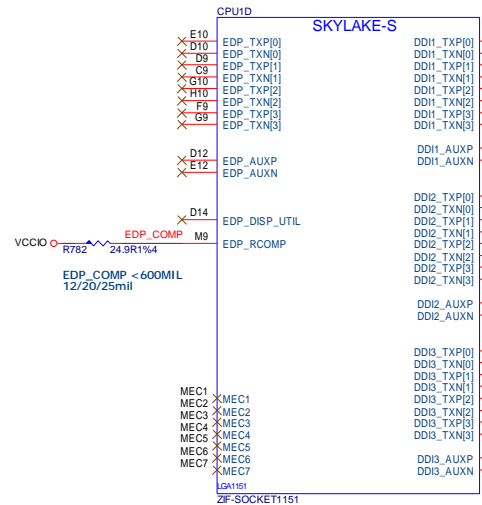
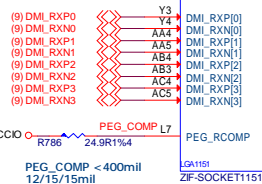
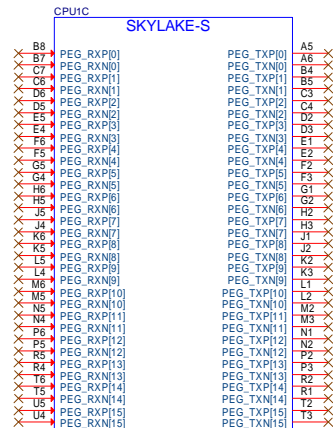
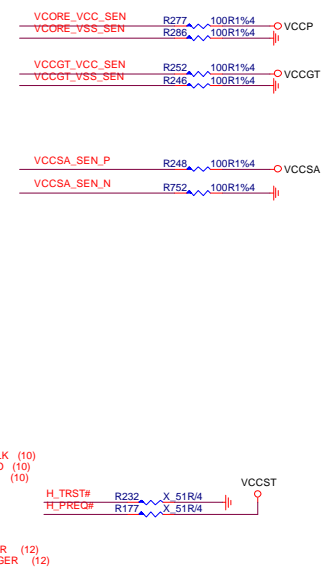
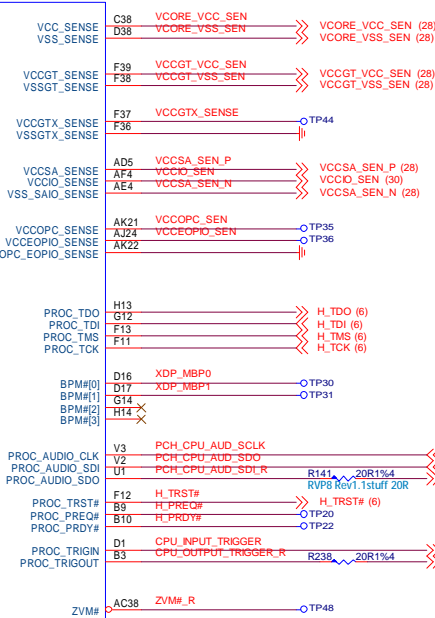
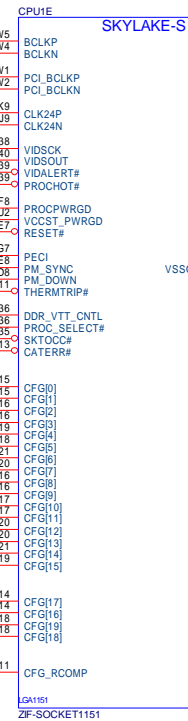
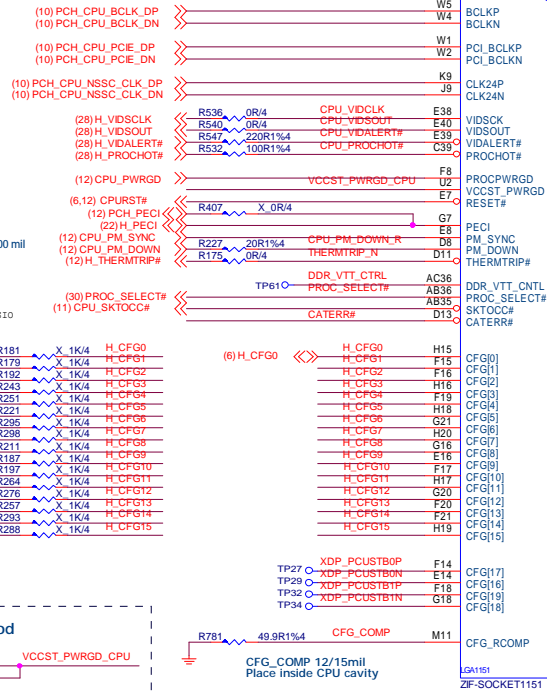
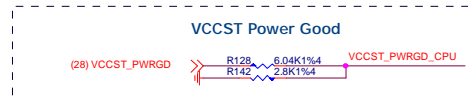


CPU-CTL/MISC/CFG/Audio/DSP



Processor Strapping
CFG[0] ITP will drive the net to GND.
CFG[2] Reserved. No connect
CFG[4] Display Port Presence strap
=1: Disabled - No Physical Display Port attached to Embedded DisplayPort*. No connect for disable.
=0: Enabled - An external Display Port device is connected to the Embedded Display Port.
CFG[5,6] (1, 1) PCIe 16X
CFG[19:5] Reserved configuration lands
A test point be placed on the board for these lands

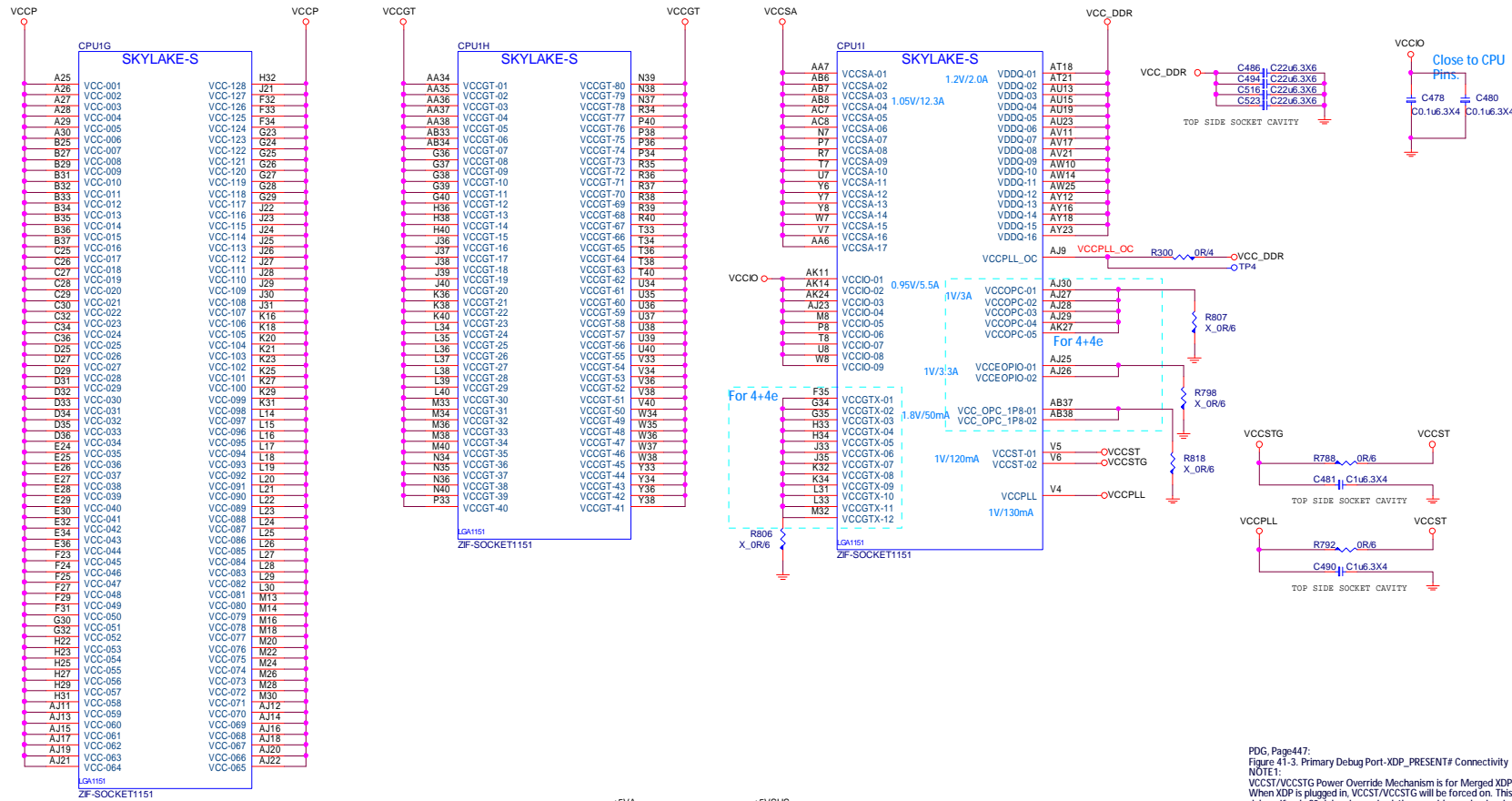
CRB1.0 Note
PD CFG9 FOR HASWELL INTERPOSER
PD CFG12 FOR HASWELL INTERPOSER
PD CFG13 FOR LPT-H INTERPOSER



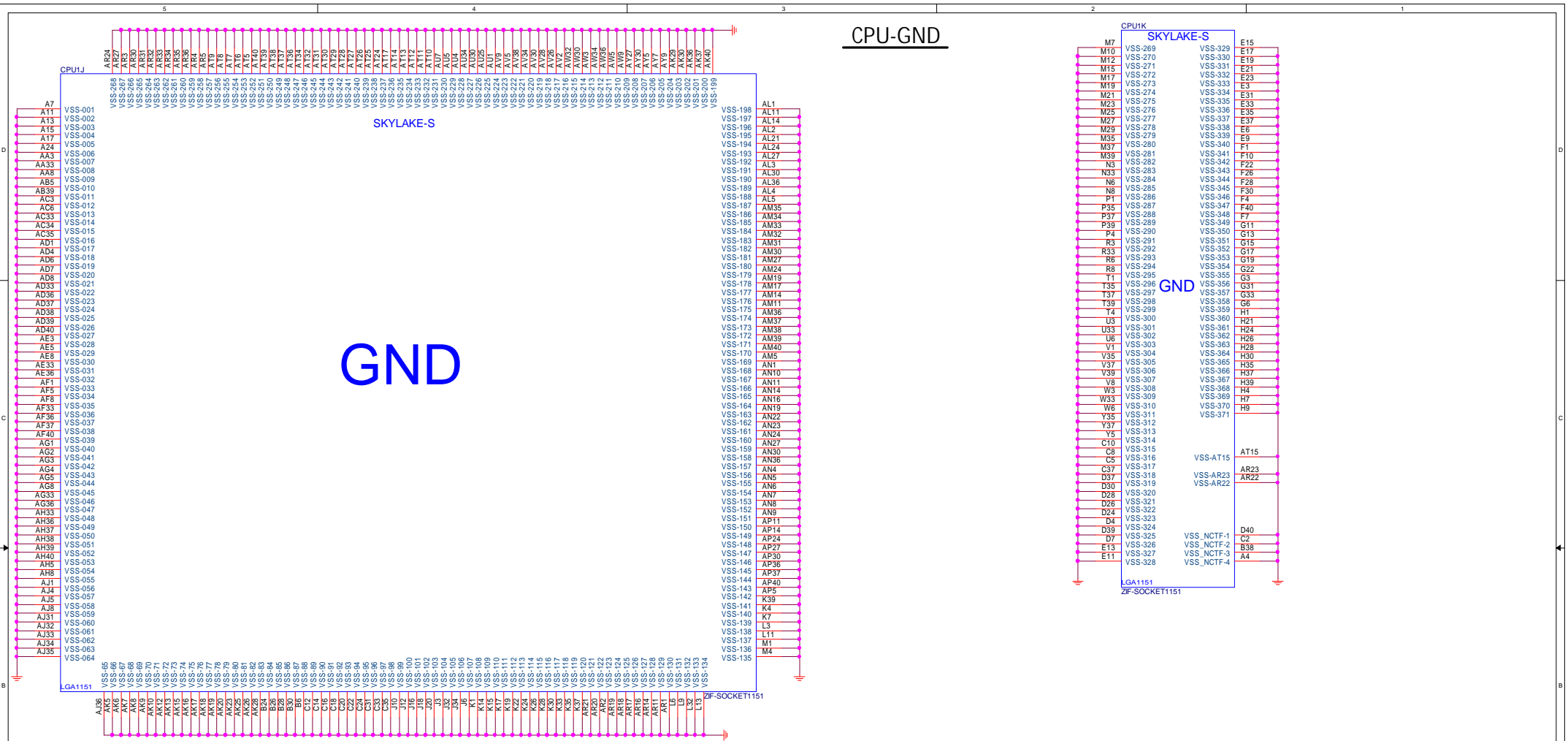
(7) MEM_MA_ADD[16..0] <<—



CPU-Power

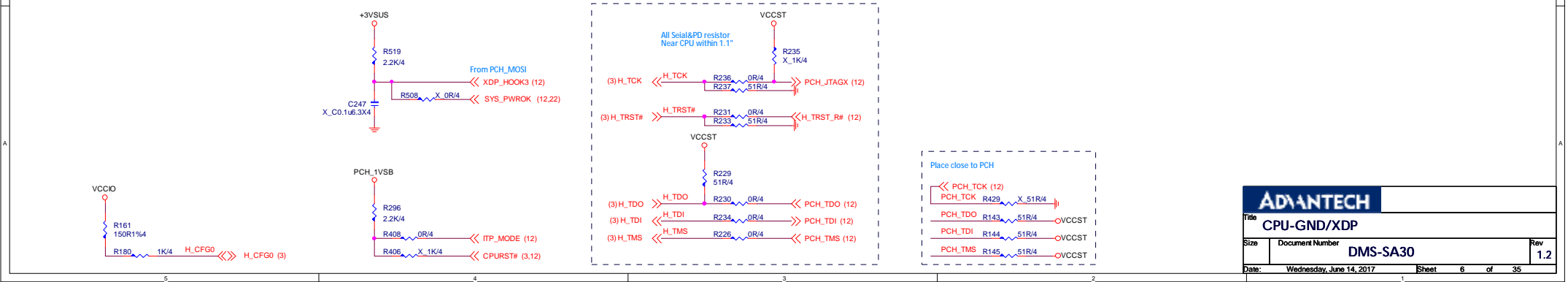


PDG, Page447:
Figure 41-3. Primary Debug Port-XDP_PRESENT# Connectivity
NOTE1:
VCCSTG/VCCSTG Power Override Mechanism is for Merged XDP usage model.
When XDP is plugged in, VCCSTG/VCCSTG will be forced on. This is to support PCH Sx debug. If only S0 debug is required, the override mechanism is not required unless C10 debug support is also needed.
NOTE 2:
XDP_PRESENT#/XDP_PRESENT_PCH connection to 2 pin header on some Intel reference design is optional. It is only used for Intel power-on.
NOTE 3:
Use Existing Override Logic. Don't have to add new logic, just connect Override Logic to the VccSTG/G-U power gating logic already in the board
Note 4... just a representation... maybe be FET or Integrated Load Switch

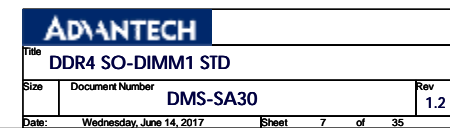


CPU-XDP

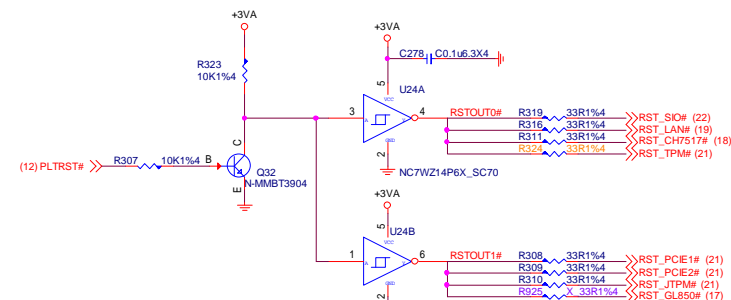
Defensive Design



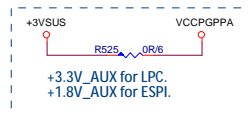
Channel A (W/O ECC)



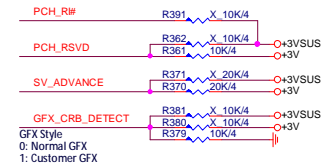
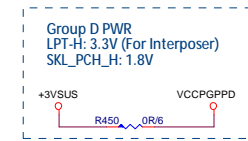
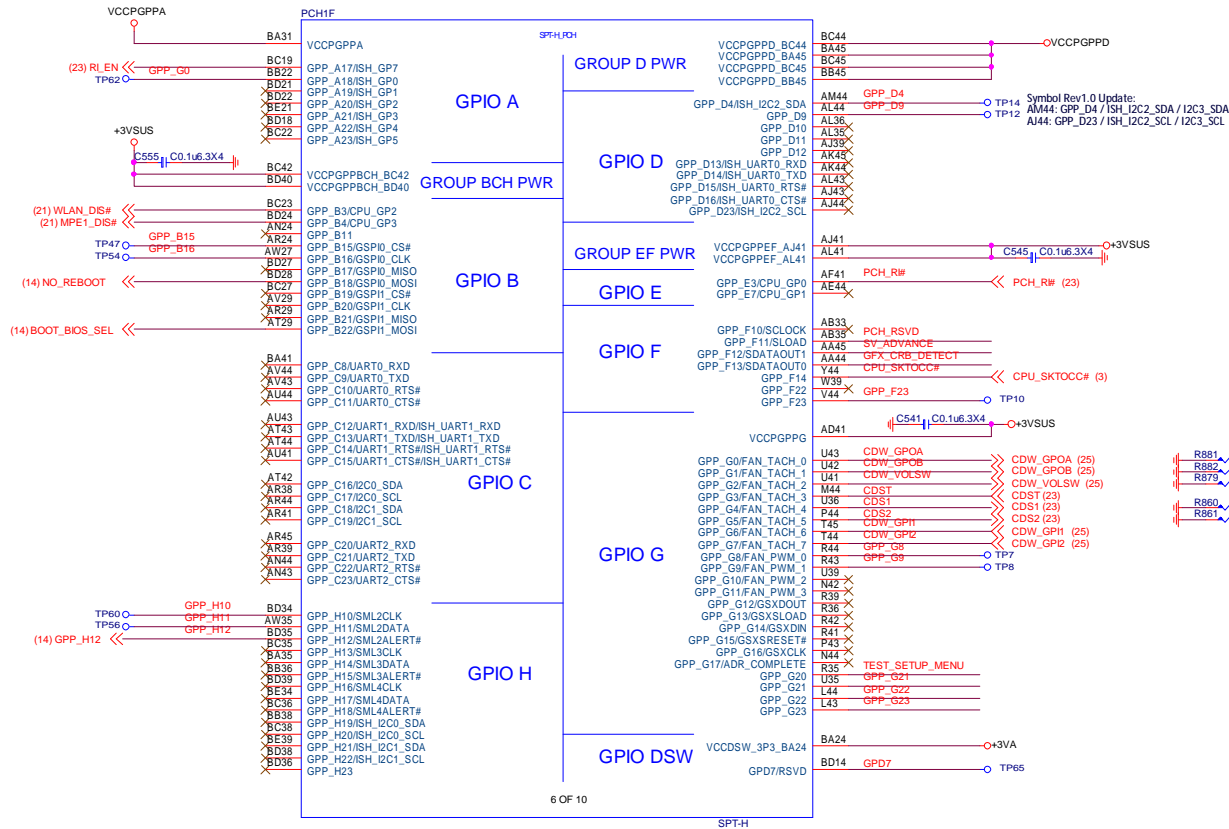
USB1~2 for Rear USB3.0(LAN_USB1)
USB3~4 for Rear USB3.0(COM_USB1)

[illegible]

PCH-GPIO



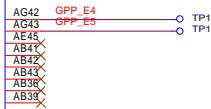
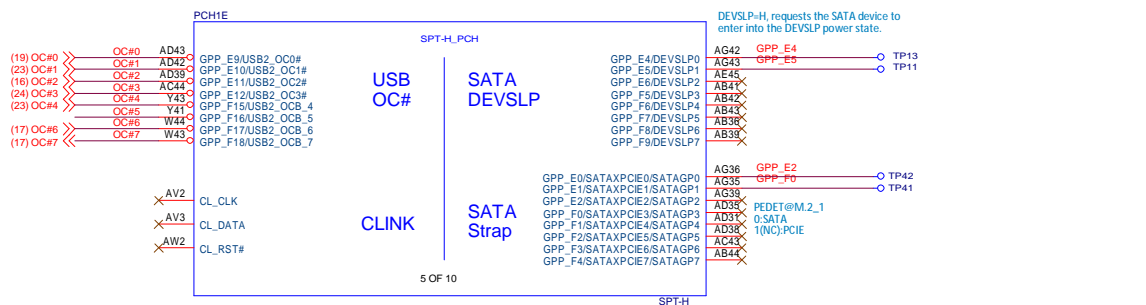
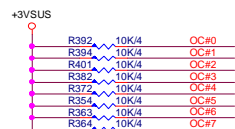
WLAN_DIS# Pull-up to +3V
with 8.2KR @connector
side.
MIPE1_DIS# Pull-up to +3V_TV
with 8.2KR @connector side.



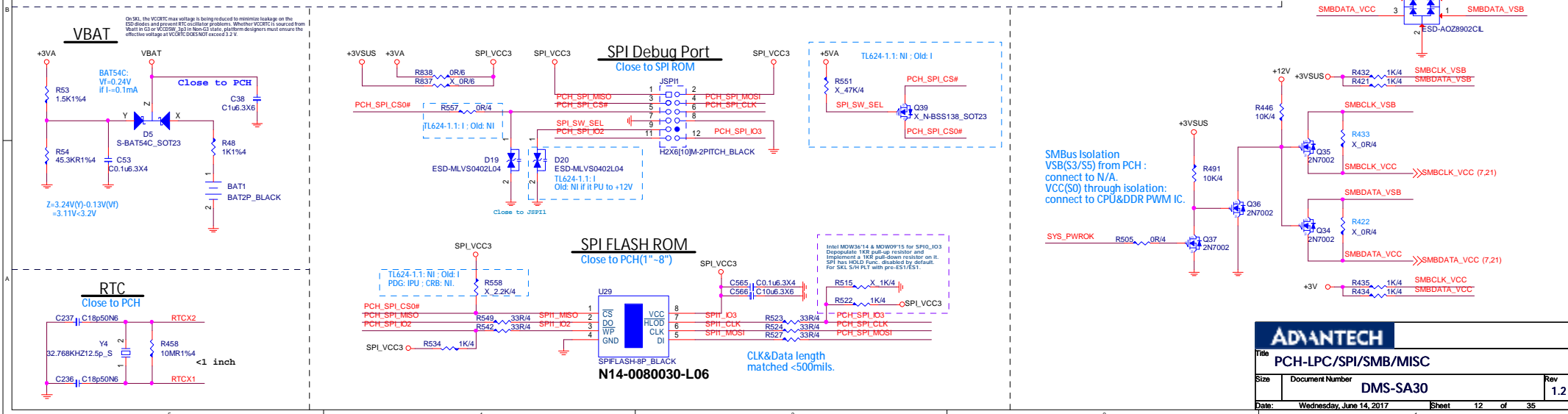
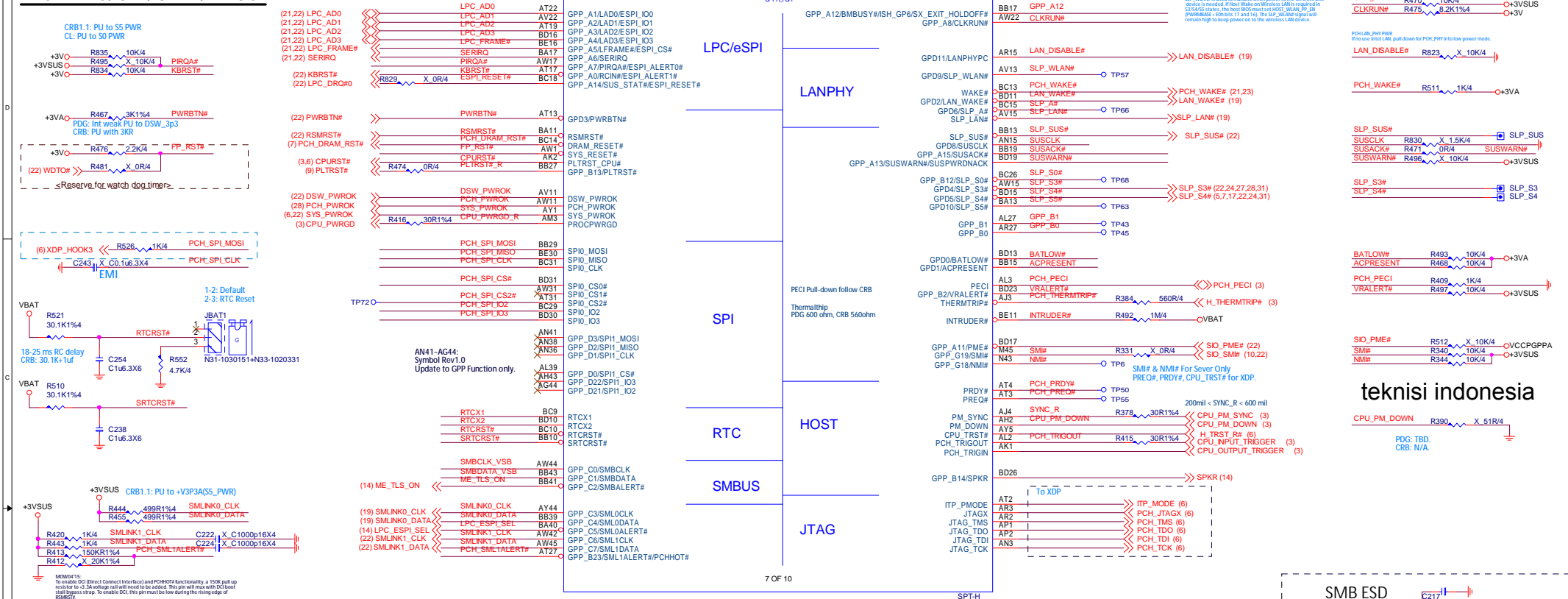
Test Setup Menu
0: Enable
1: Disable



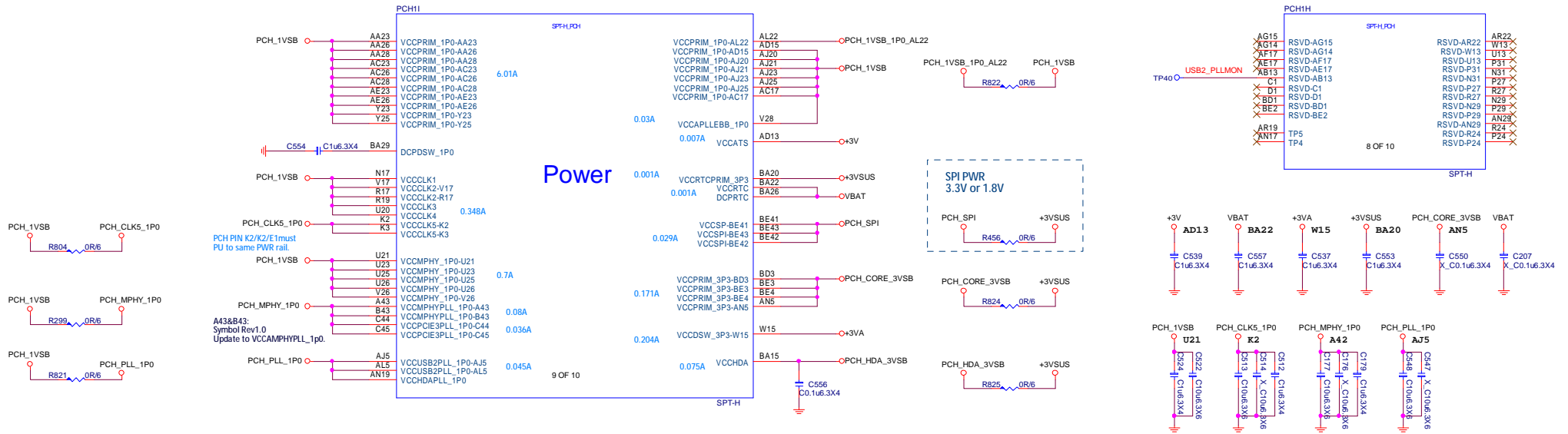
PCH-USB_OC & SATAGP



PCH-LPC/SPI/SMB/MISC



PCH-Power



TPM - SLB9670VQ2.0 (SPI I/F)

<Reserve>

GND

PCH-GND

PCH-Strap

For Strapping pull-up resistor
CRB1.1: 4.7K
PDG2.1: 1-2.2K

Top Swap(SPKR/GPP_B14)



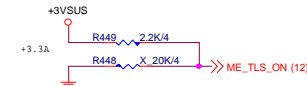
This signal has an integrated weak pull-down resistor (20 K Ω nominal) to disable Top-Block Sway by default.
To enable Top-Block Swap, this signal should be pulled up to V3.3S through a 1k to 2.2 K Ω \pm 5% resistor.

No Reboot(GSPI0_MOSI/GPP_B18)



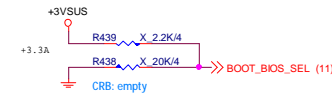
This signal has an integrated weak pull-down resistor (20 K Ω nominal) to disable the no reboot strap functionality by default.
To enable no reboot on TCO Timer expiration, this signal should be pulled-up to V3.3S through a 1k to 2.2 K Ω \pm 5% resistor.

Intel ME Crypto Transport Layer Security (TLS-SMBALERT#/GPP_C2)



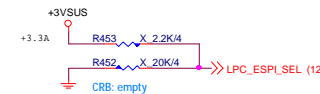
This signal has an integrated weak pull-down resistor (20 K Ω nominal) to disable IntelR ME Cryptographic Transport Layer Security (TLS) cipher suite (no confidentiality).
To enable IntelR ME Cryptographic Transport Layer Security (TLS) cipher suite with confidentiality, this signal should be pulled up to V3.3A through a 1k to 2.2 K Ω \pm 5% resistor.

Boot BIOS Strap Bit (GSP11_MOSI/GPP_B22)



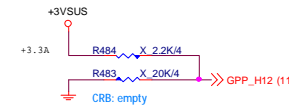
This signal has an integrated weak pull-down resistor (20 K Ω nominal) to default boot from SPI. To enable boot to LPC, this signal should be pulled up to V3.3S through a 1k to 2.2 K Ω \pm 5% resistor.

ESPI/LPC SEL Strap(SMLOALERT#/GPP_C5)



This signal has a weak internal pull-down.
0 = LPC is selected for EC. (Default)
1 = eSPI is selected for EC.
Notes:
1. The internal pull-down is disabled after RSMRST# de-asserts.
2. This signal is in the primary well.

ESPI Flash Sharing Mode(GPP_H12)



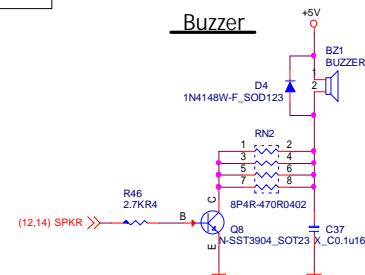
This signal has a weak internal pull-down. This strap should sample LOW. There should NOT be any on-board device driving it to opposite direction during strap sampling.
Note: The pull-down resistor is disabled after RSMRST# de-asserts

SPIO_MOSI & SPIO_MISO:
This signal has an internal pull-up.
This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling(RSMRST#).

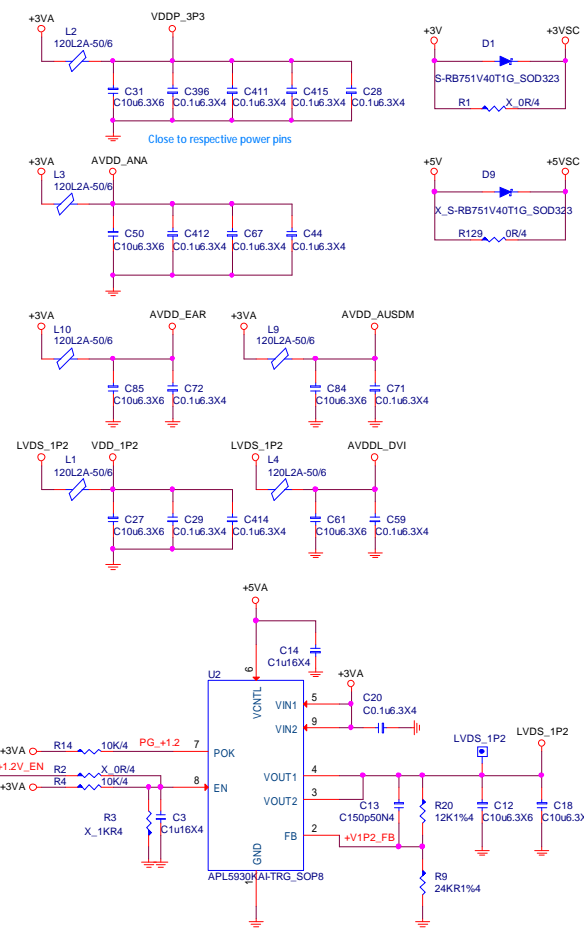
SML1ALERT# /PCHHOT#/GPP_B23:
This signal has an internal pull-down.
This strap should sample LOW. There should NOT be any on-board device driving it to opposite direction during strap sampling(RSMRST#).

SPIO_IO2 & SPIO_IO3:
This signal has an internal pull-up.
This strap should sample HIGH. There should NOT be any on-board device driving it to opposite direction during strap sampling(RSMRST#).

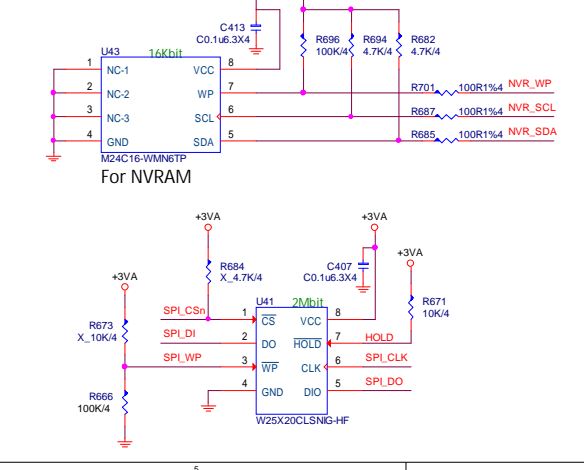
Buzzer



ADVANTECH		
Title PCH-GND/Strap		
Size	Document Number	Rev
	DMS-SA30	1.2
Date:	Wednesday, June 14, 2017	Sheet 14 of 35

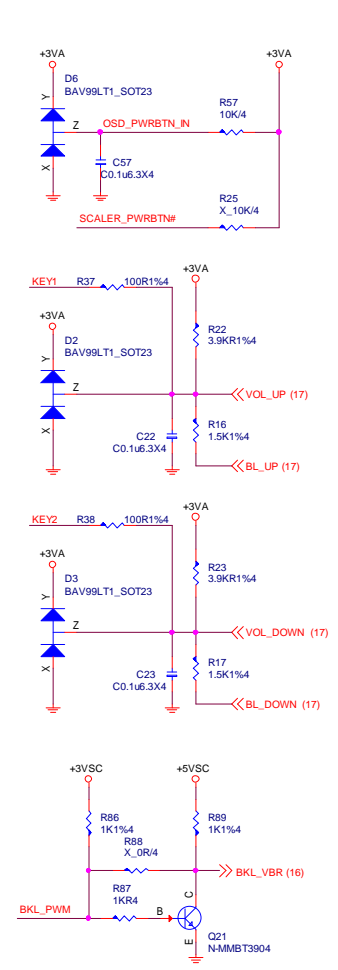
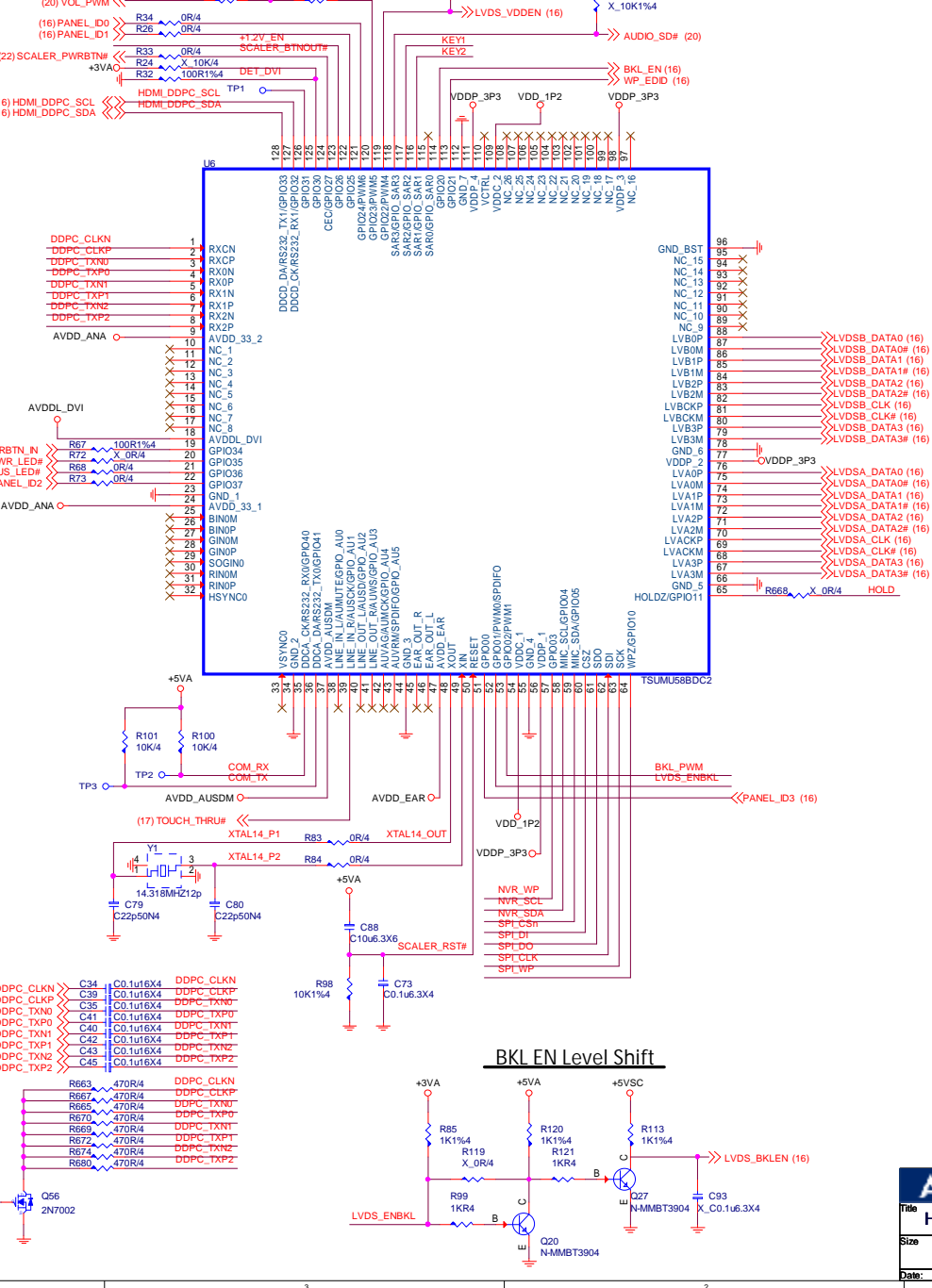


NVRAM & SPI ROM

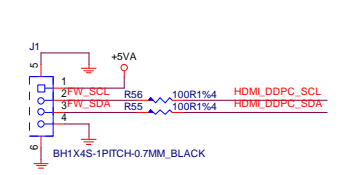


Scaler

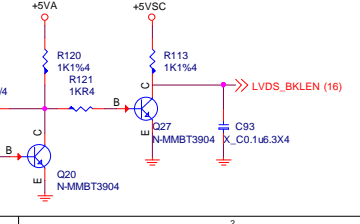
TSUMU58BDC



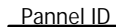
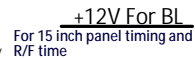
F/W Update



BKL EN Level Shift



R3C-0000012-W08 Co-layout with L12-9008090-M09
Note. The pin's definition between R&L are difference.



Panel ID 0~3 controlled by LVDS cable.



(15) WP_EDD1

WP_EDD15

R135 X 0R/4

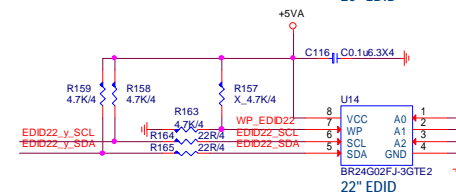
D10 WP_EDD15

S-RB751V40T1G SOD323 D11 WP_EDD17

S-RB751V40T1G SOD323 D12 WP_EDD20

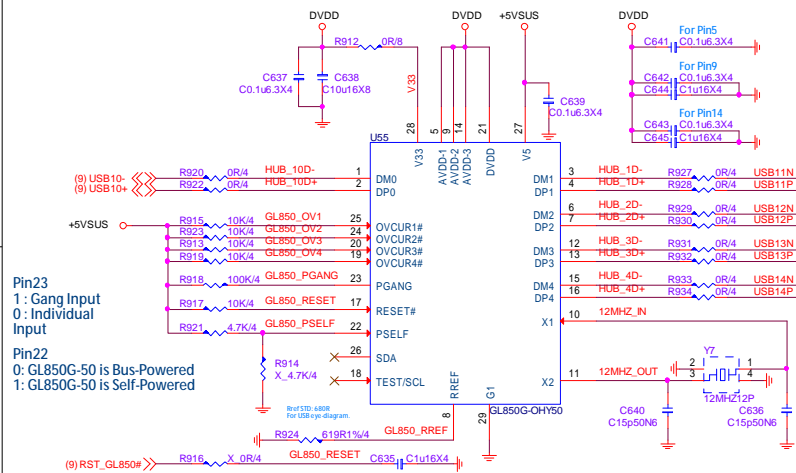
S-RB751V40T1G SOD323 D13 WP_EDD22

S-RB751V40T1G SOD323 D15 WP_EDD23



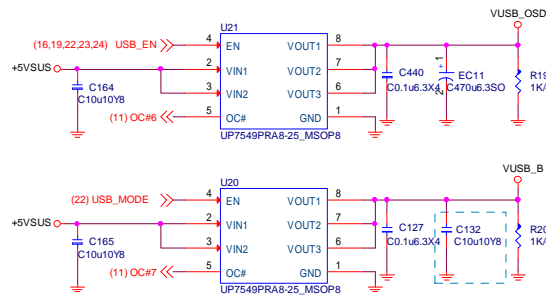
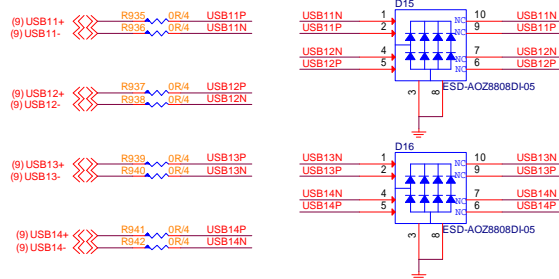
GL850G - USB2.0 HUB

USB Port 10 For H110 Sku

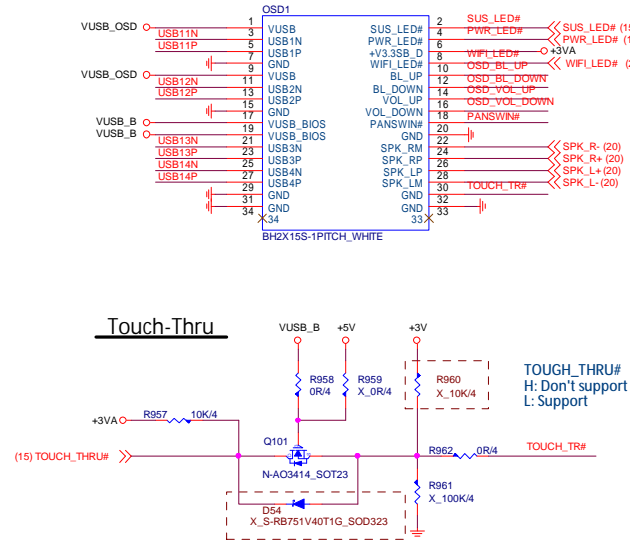


USB Signal & PWR For OSD Conn.

USB Port 11~14 For Q170 Sku

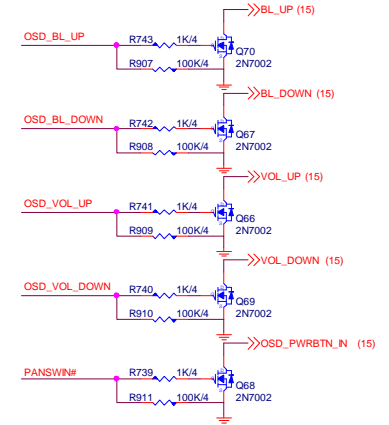


OSD & LED & SPK & USB2.0*4 Conn.

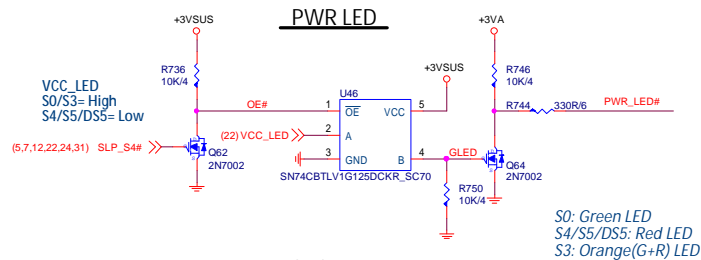


Touch-thru feature: Typical functionality is:
1. After pressing the "Volume Down" and "Brightness Up" buttons together for 3 seconds, the Touch-thru control status will display as long as the two buttons are pressed.
2. Pressing the "Volume Down" and "Brightness Up" buttons together for ANOTHER 3 seconds toggles the Touch-thru control status between OFF and ON.
3. The Touch-thru feature is "OFF" as default setting.

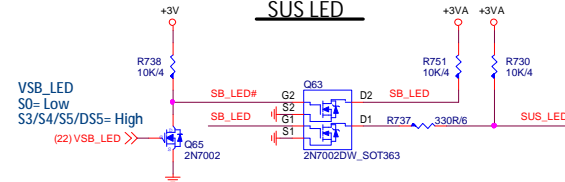
BL & VOL Control



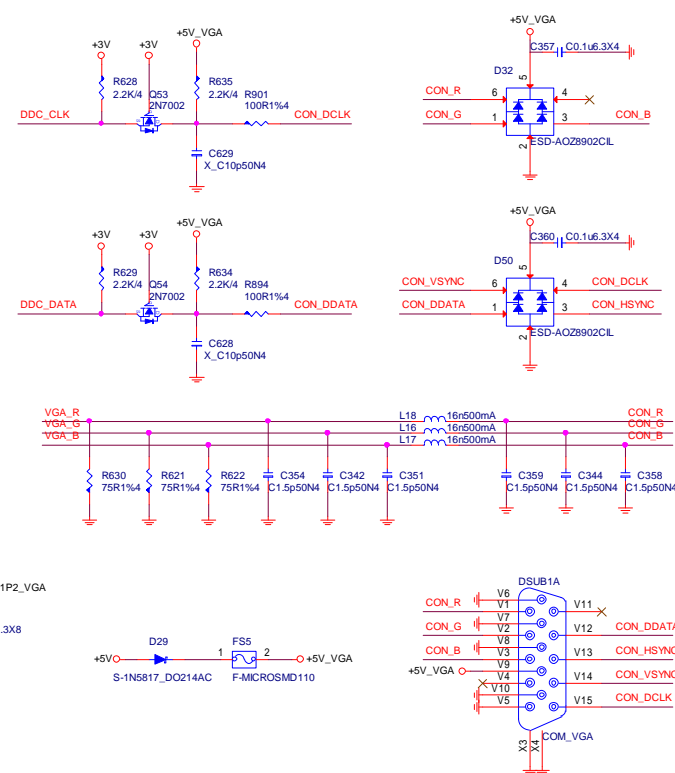
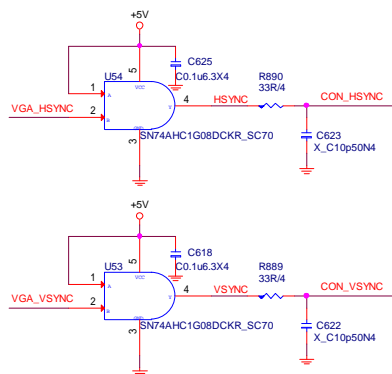
PWR LED



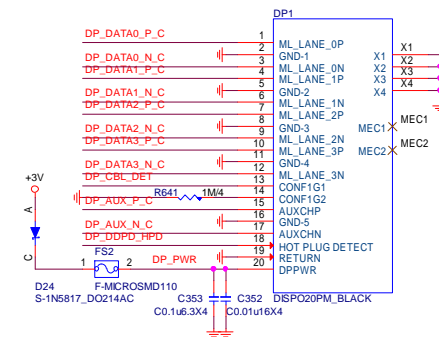
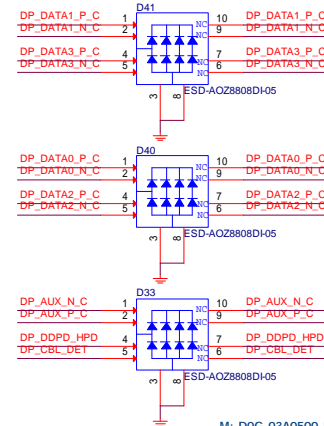
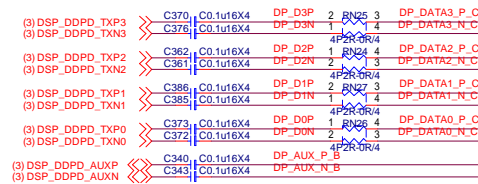
SUS LED



EMI caps (close to OSD1)		
C428	X	C0.1u6.3X4 SUS_LED#
C454	X	C0.1u6.3X4 PWR_LED#
C427	X	C0.1u6.3X4 WFL_LED#
C437	X	C0.1u6.3X4 OSD_BL_UP
C436	X	C0.1u6.3X4 OSD_BL_DOWN
C435	X	C0.1u6.3X4 OSD_VOL_UP
C434	X	C0.1u6.3X4 OSD_VOL_DOWN
C433	X	C0.1u6.3X4 PANSWIN#
C426	X	C0.1u6.3X4 SPK_R-
C425	X	C0.1u6.3X4 SPK_R+
G121	X	C0.1u6.3X4 SPK_L+
C122	X	C0.1u6.3X4 SPK_L-



$V_{OUT} = V_{REF} \times (R_1 + R_2) / R_1$
 $= 0.8 \times (20 + 10) / 20 = 1.2V$



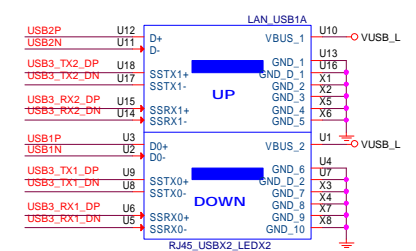
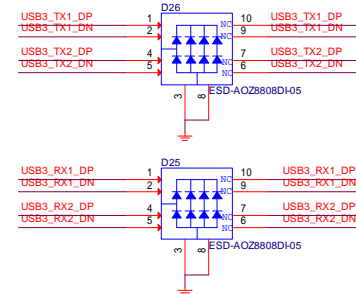
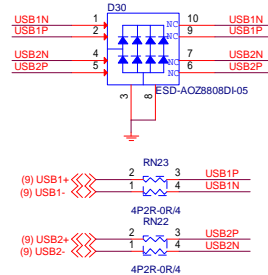
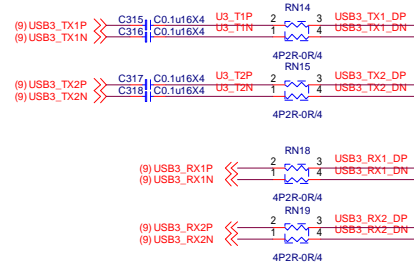
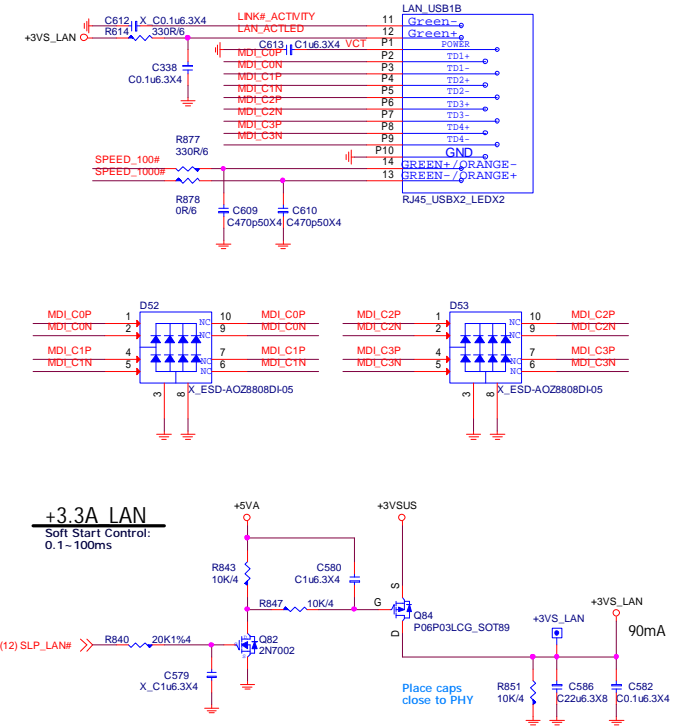
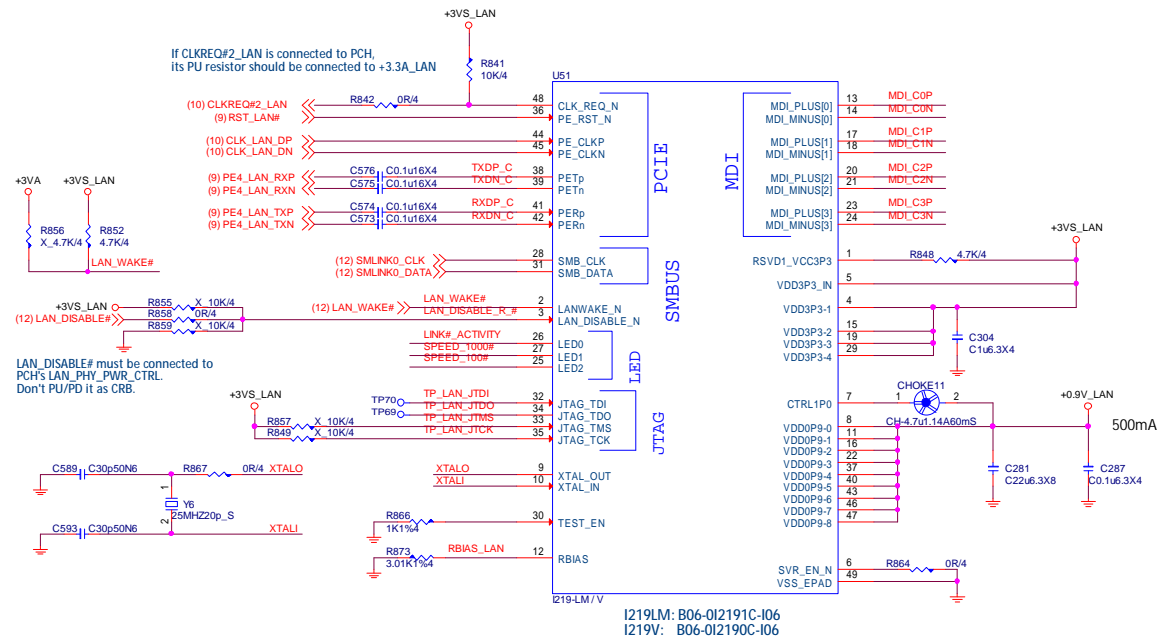
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S: DOG-06A050C-A68
S: DOG-05A0300-I14

Title **VGA(CH7517A) & Mini DP**

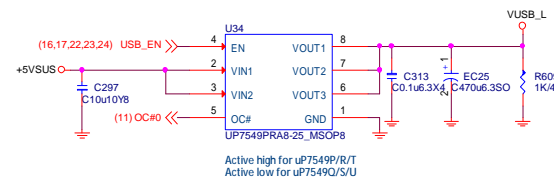
Size	Document Number
	DMS-SA30

Date: Wednesday, June 14, 2017 Sheet 18 of 35

Intel LAN I219-V/LM



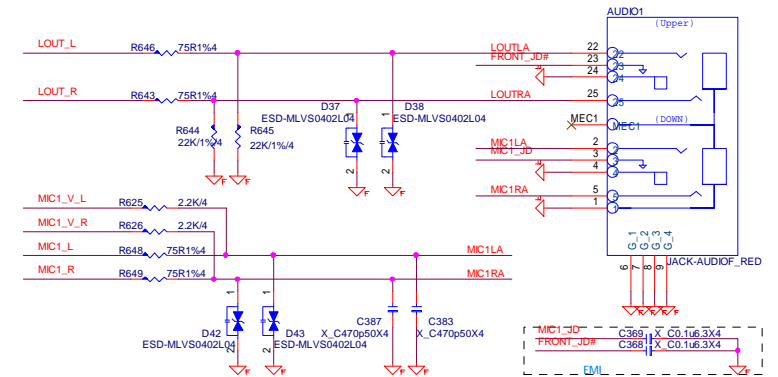
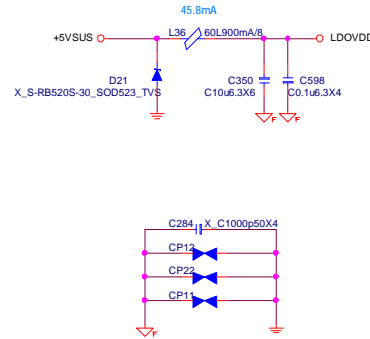
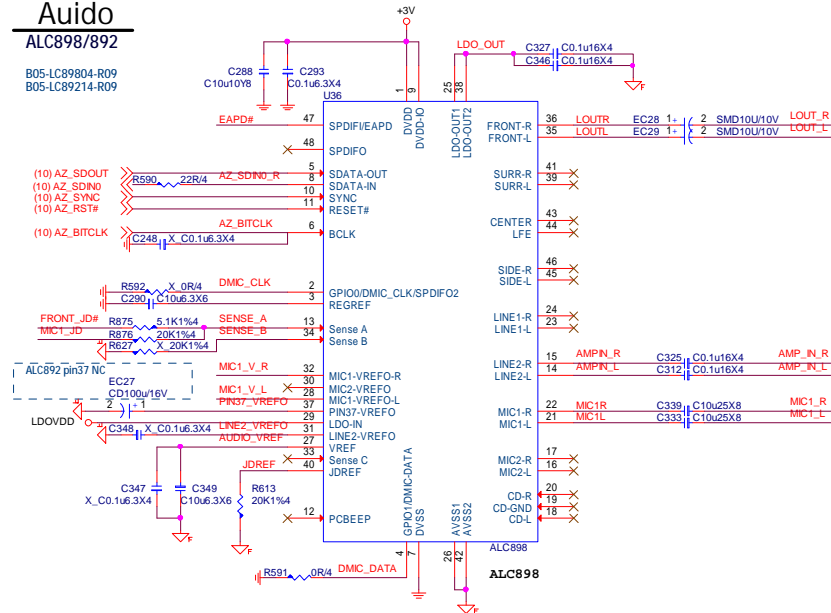
www.teknisi-indonesia.com



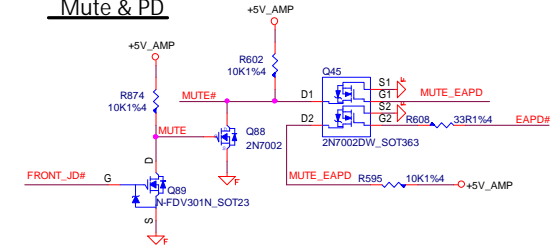
Auido

ALC898/892

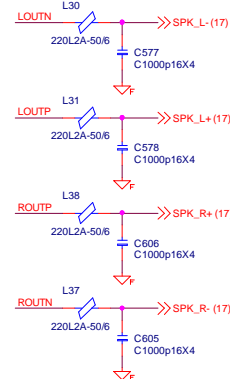
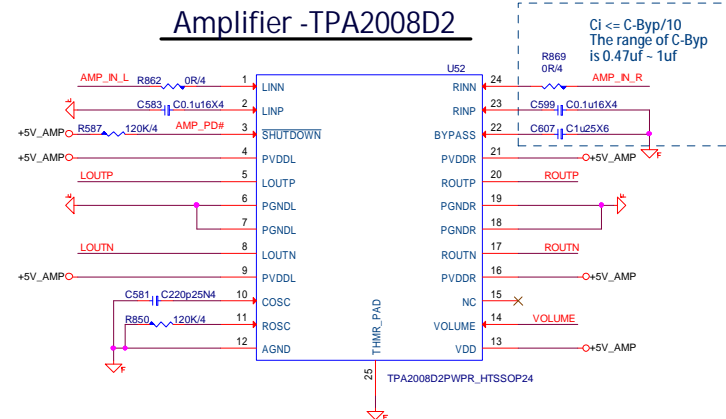
B05-LC89804-R09
B05-LC89214-R09



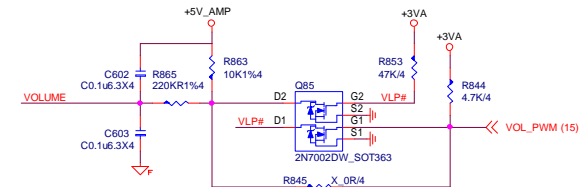
Mute & PD



Amplifier -TPA2008D2



VOL PWM Level Shift



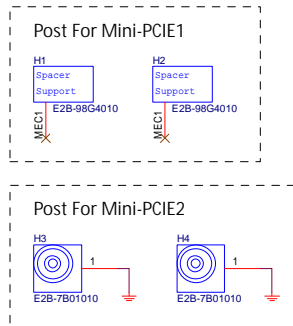
ADIANTECH

Audio Codec ALC898/AMP

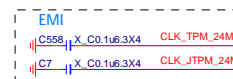
DMS-SA30

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Full size (No.19)

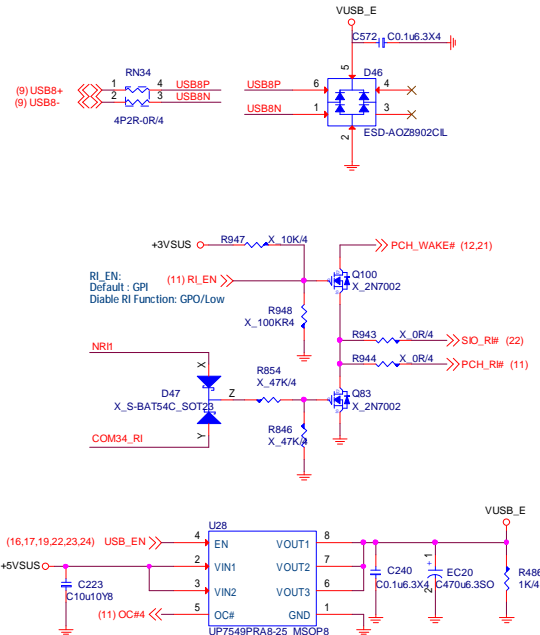
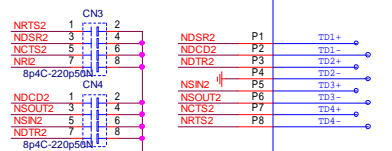
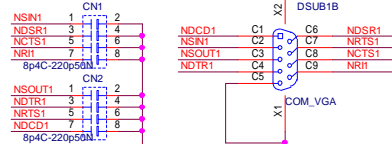
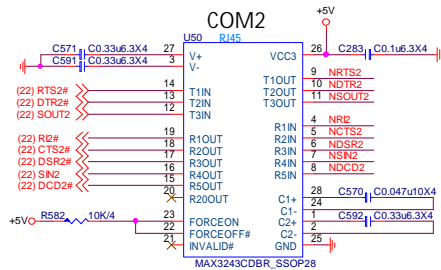
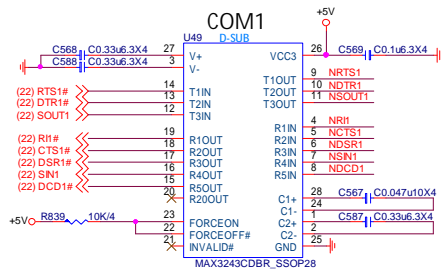


Standard (No.13)

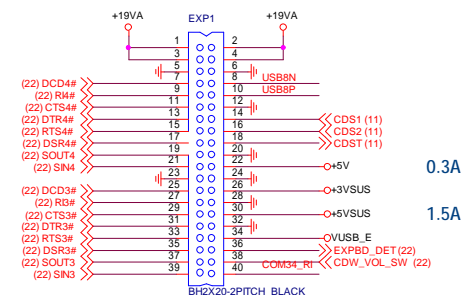


ADVANTECH			
Title Mini PCI-E & TPM & JTPM/JLPC & USB2.0*1			
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Date:	Wednesday, June 14, 2017	Sheet 21 of 35	

COM 1&2 MAX3243CDBR



Expansion BD Conn. COM3&4

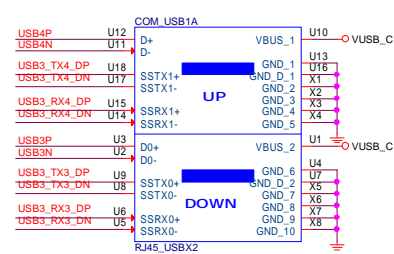
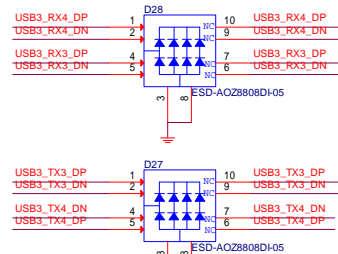
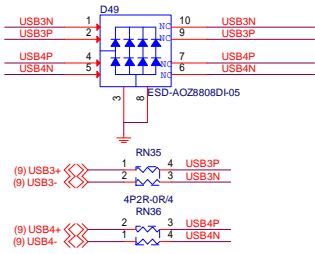
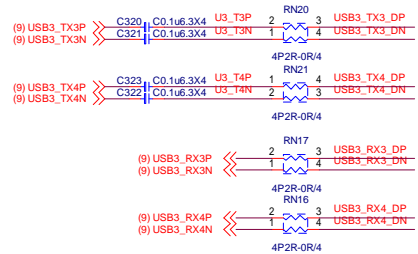


CDS1 & CDS2 :
Cash drawer GPIO output to expansion BD.
Default=Low, this GPIO controlled by AP.

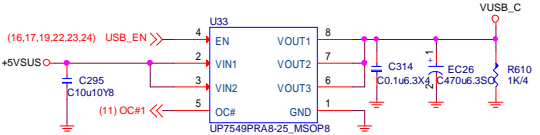
CDST :
Cash drawer status input from expansion BD.
Default=H (Drawer open=Low ; close=High)

EXPBD_DET
No EXP. BD.= High -> Disable COM3&COM4
Insert EXP. BD.= Low -> Enable COM3&COM4

CDW_VOL_SW
+24VSB/+12VSB selection output for expansion BD.
Default=H, it controlled by BIOS setup manual

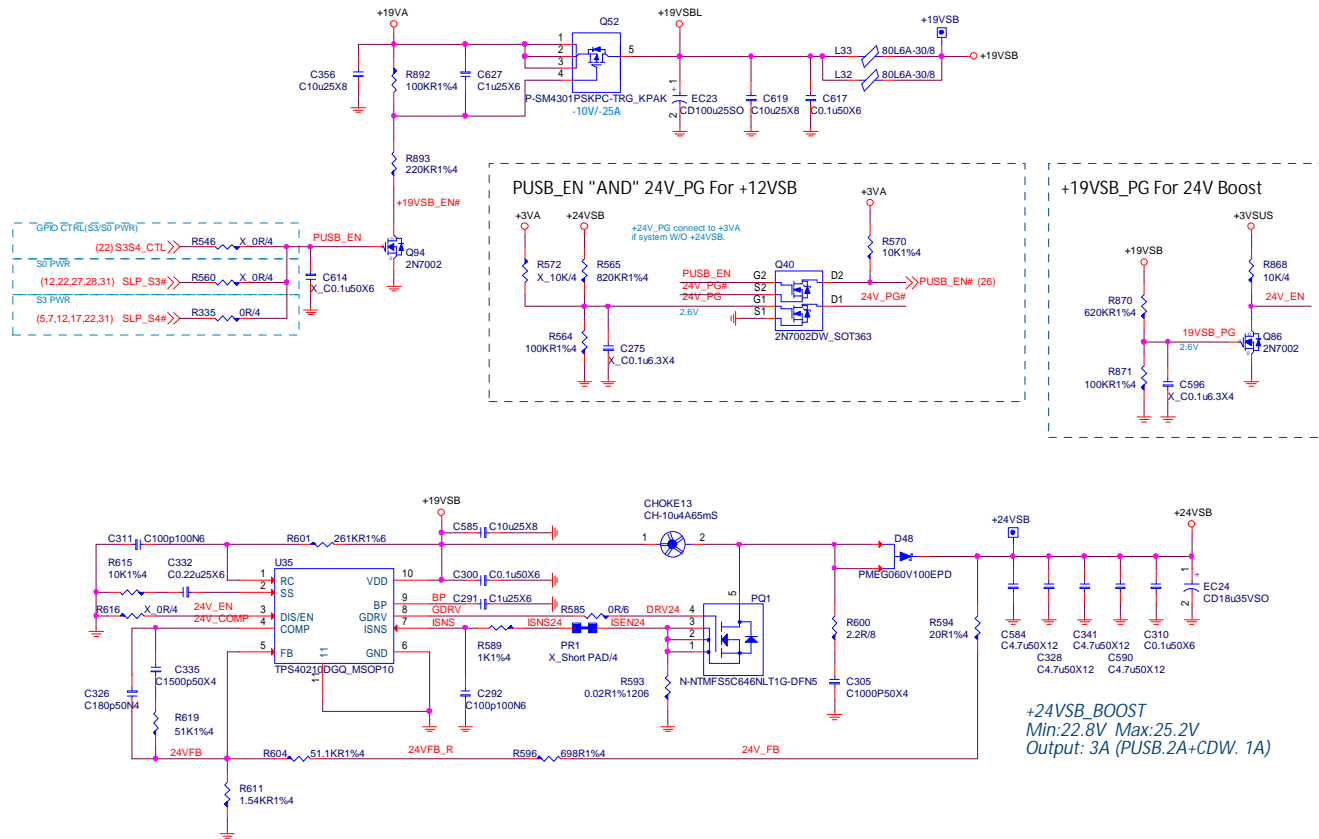


RJ45(COM+USB)
USB3.0: N58-26F0031-S42
USB2.0: N58-16F0291-S42



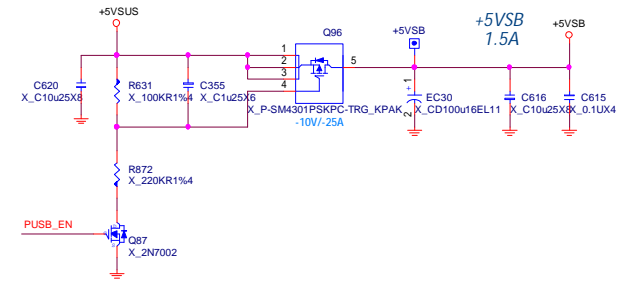
+24V Boost (S3/S0 PWR)

TPS40210



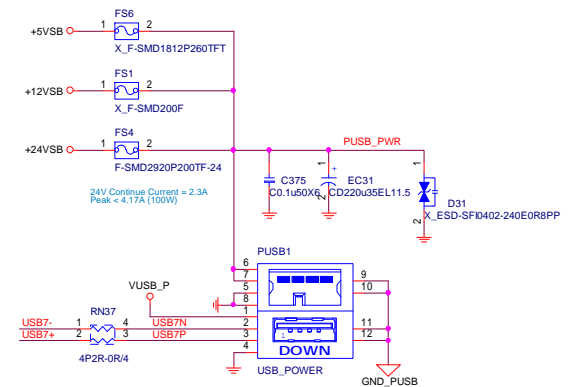
+5VSB (S3/S0 PWR)

Reserve for FS6 of PUSB



Power USB

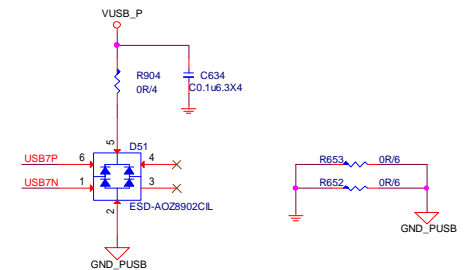
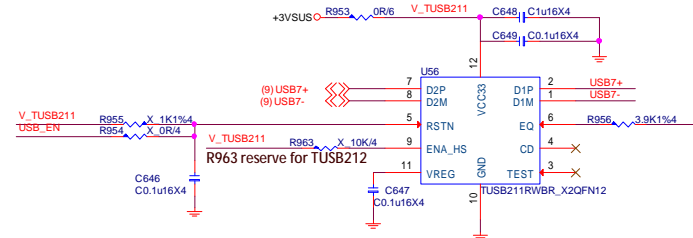
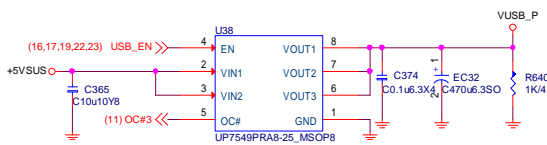
The default spec would stay with +24VSB spec as VS defined, and reserve the +12V/+5V PUSB EE design on MB for option requirement.



USB Signal & PWR For PWR USB Port 13

TUSB211 USB 2.0 HS Signal Conditioner

Reserve for 5M Certificated USB Cable



ADVANTECH

Title: +24V Boost & +5VSB & Power USB(U2*1)

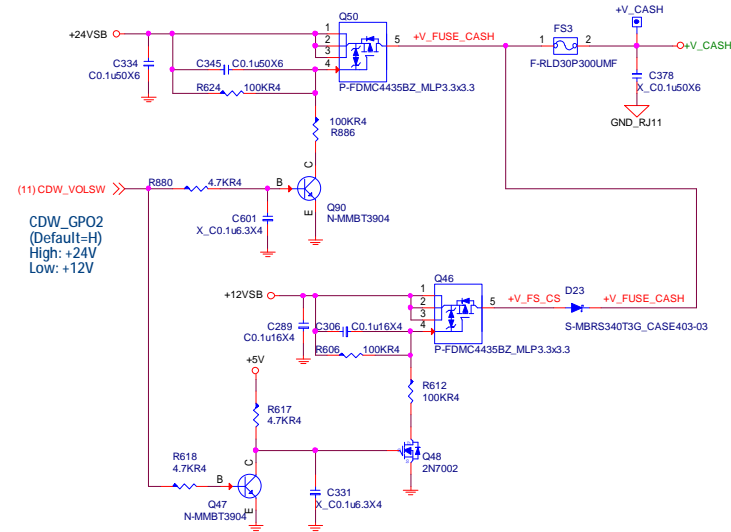
Size: Document Number: DMS-SA30

Rev: 1.2

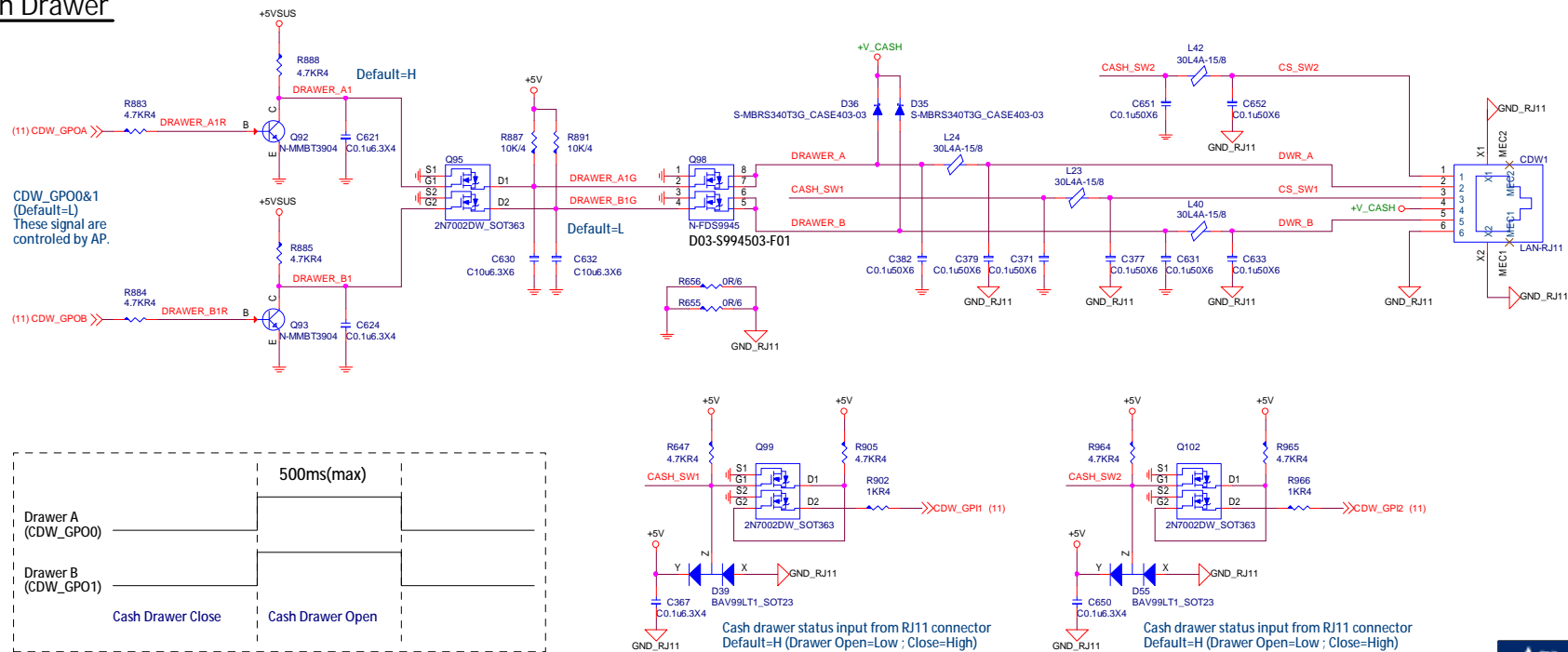
Date: Wednesday, June 14, 2017 Sheet: 24 of 35

+V_CASH Power Selection

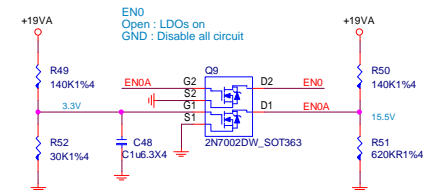
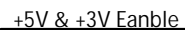
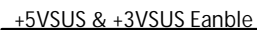
+24VSB / +12VSB



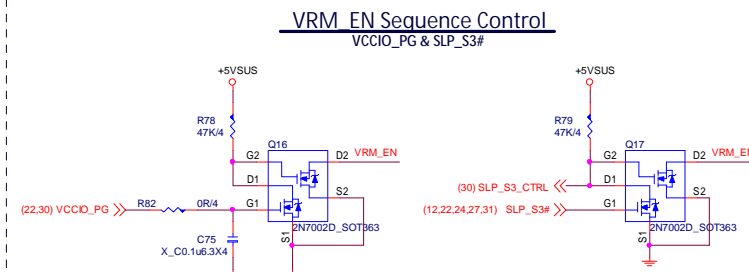
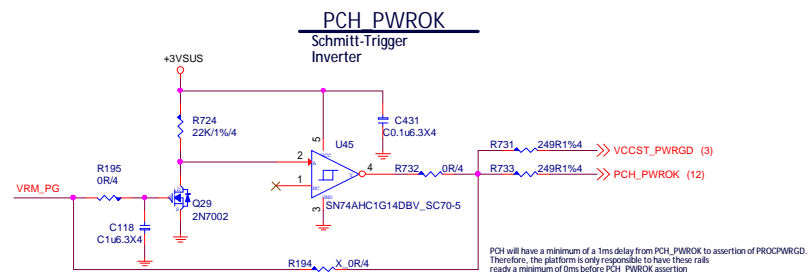
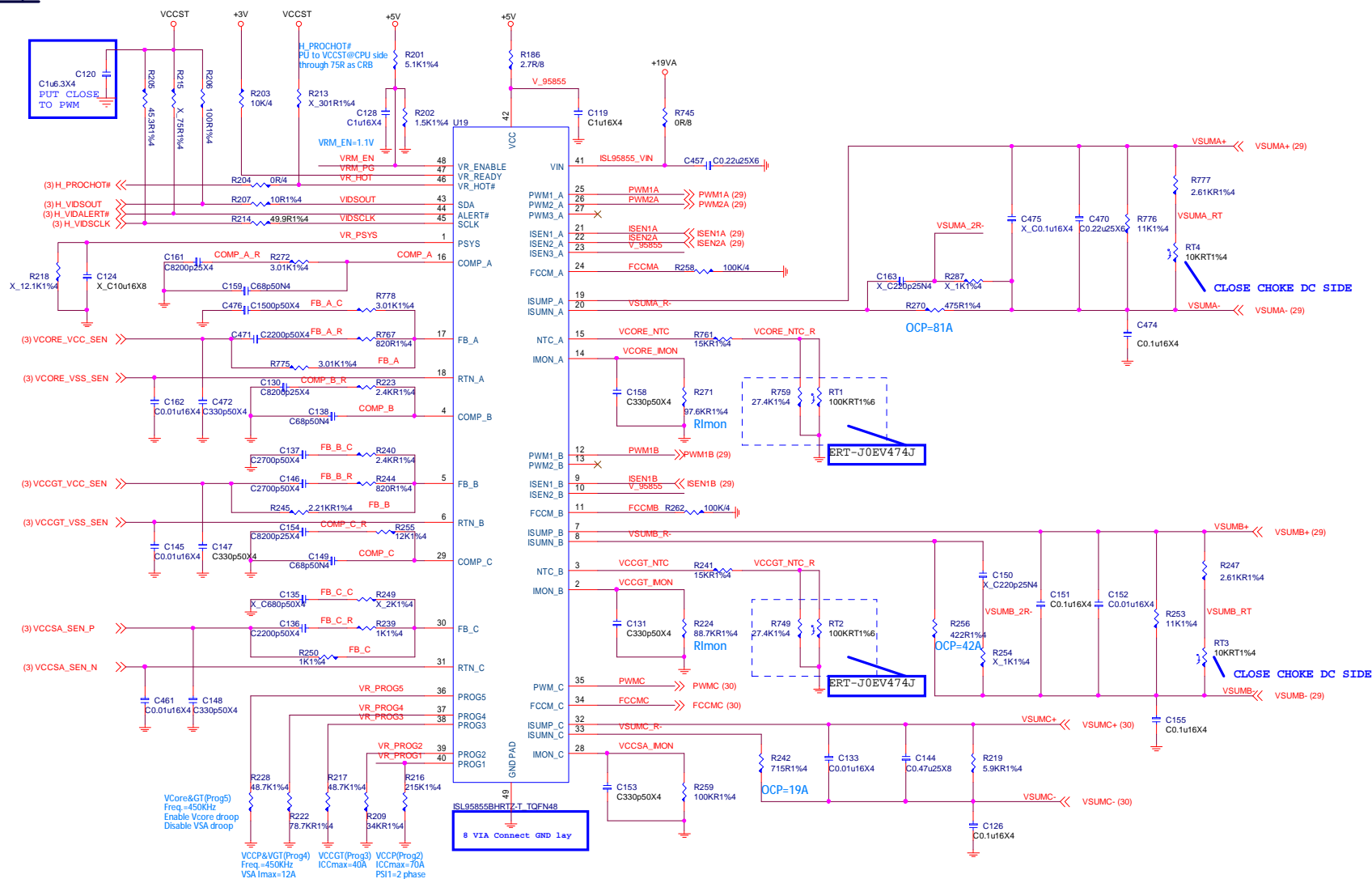
Cash Drawer



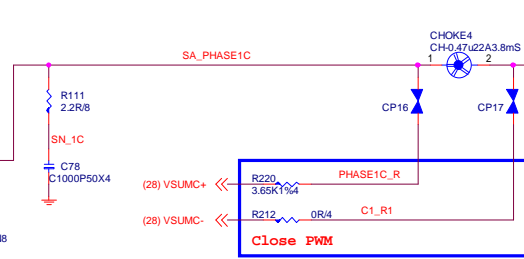
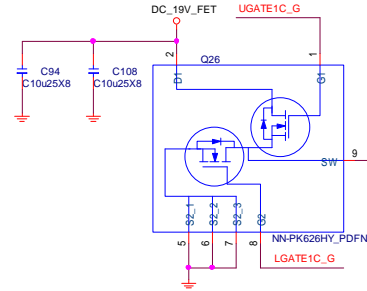
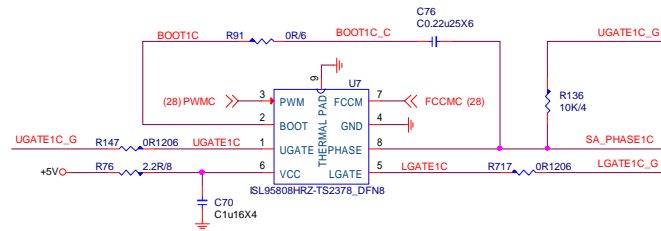
+5VSUS/+3VSUS/+5V/+3V



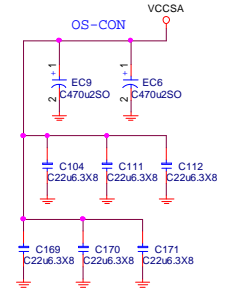
SKL S-line 35W (ISL95855B)



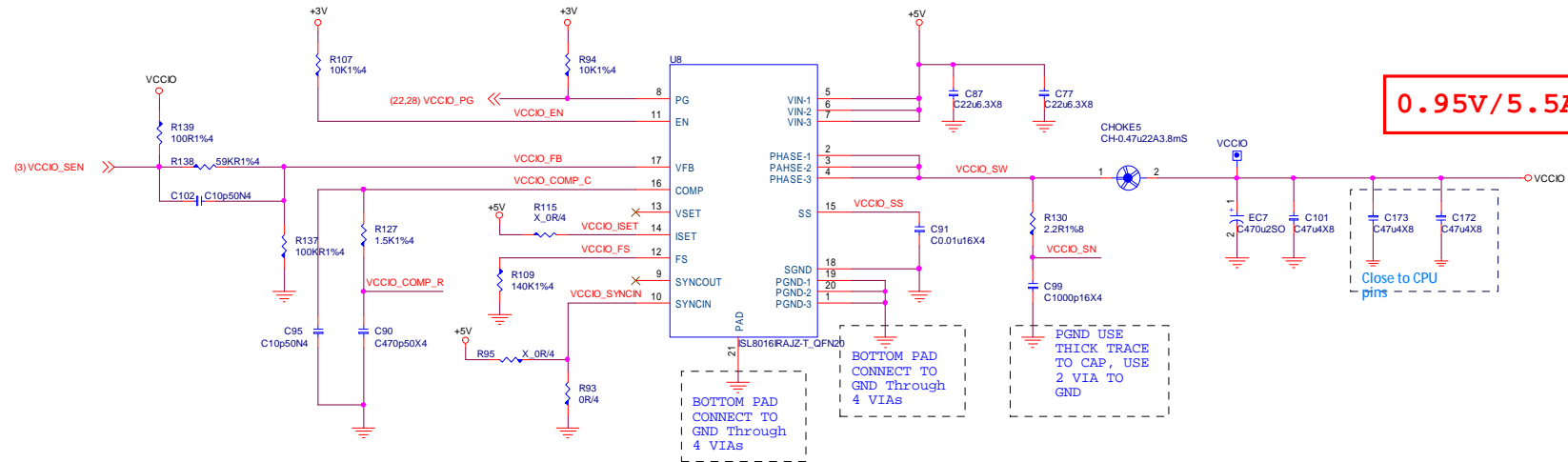
VCCSA



1.05V/11.1A



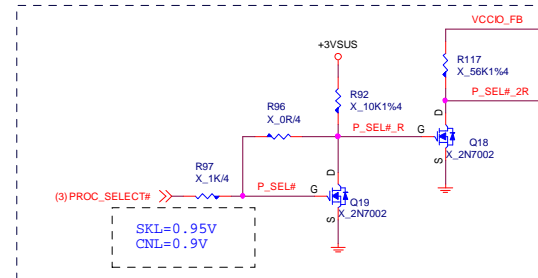
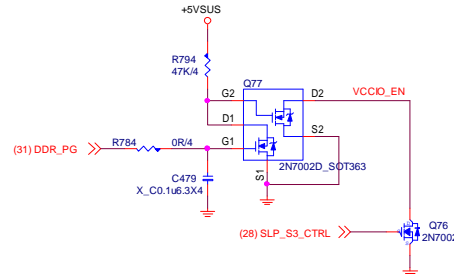
VCCIO



0.95V/5.5A

VCCIO_EN Sequence Control

DDR_PG & SLP_S3#



ADVANTECH

Title VCCSA & VCCIO

Size Document Number DMS-SA30

Date: Wednesday, June 14, 2017 Sheet 30 of 35 Rev 1.2

I9C-1727P0C-U33

CONNECT TO GND PLANE BY 4 VIAS

**2.5V
2.24A**

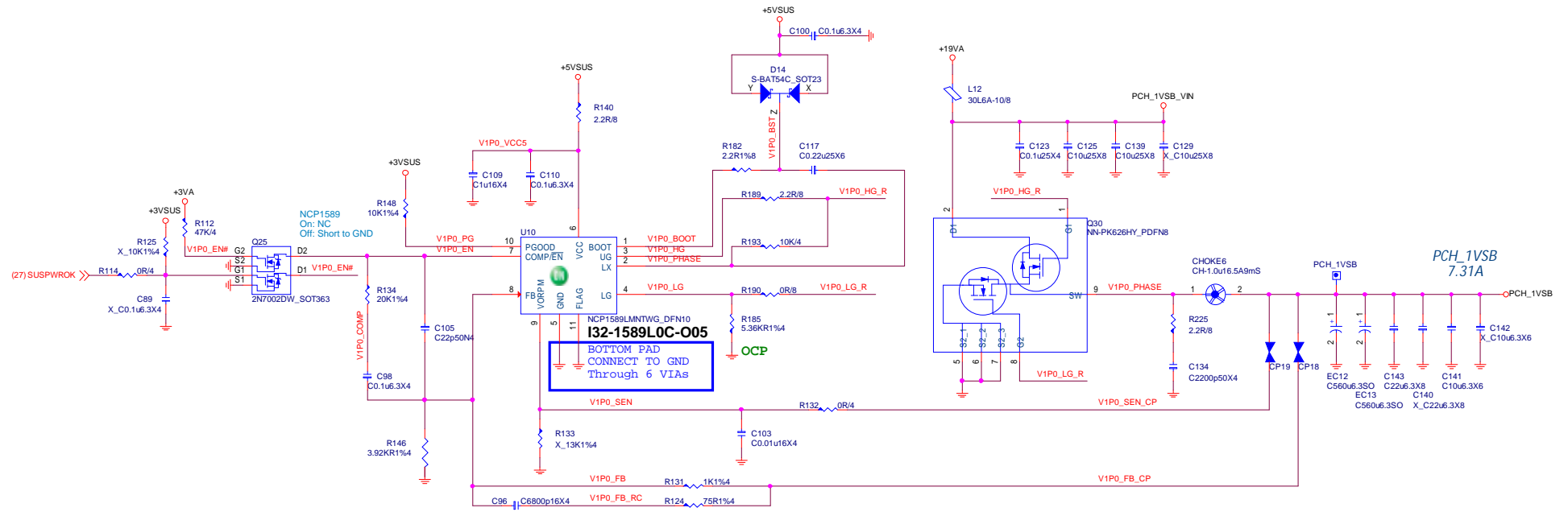
$$V_{out} = 0.6 \cdot (R1 + R2) / R2$$

$$= 0.6 \cdot (31.6K + 10K) / 10K$$

$$= 2.49V$$

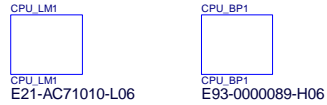
[illegible][illegible]

PCH_1VSB



CPU Socket

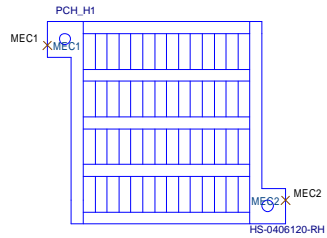
ILM + BP



PCB



PCH Heatsink



SPI ROM



BIOS1 is a 60-level option part.
<Reserve it if stuff SPI-ROM socket on U29>

BIOS Label

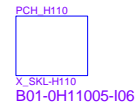


Battery

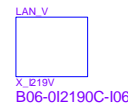


Option Parts

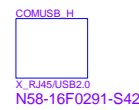
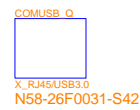
PCH Option



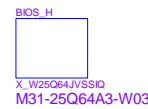
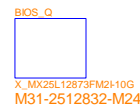
LAN Chip Option



COM_USB1 Option

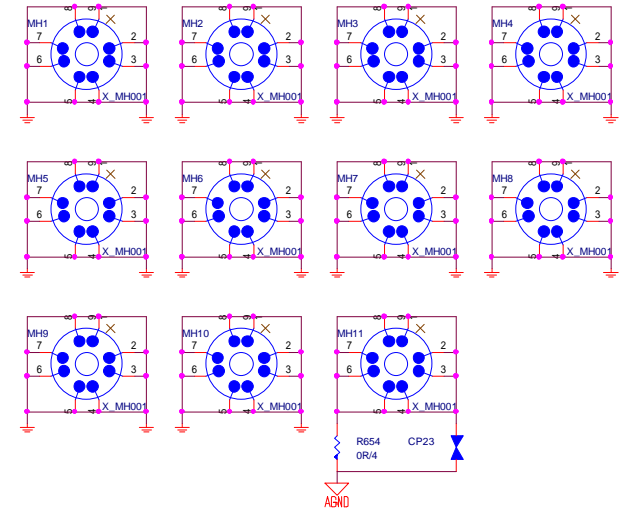


SPI ROM Option

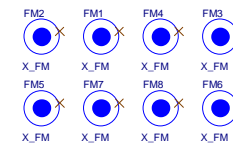


BIOS 8M (H110) : M31-25Q6443-W03
BIOS 16M (H170/Q170) :
M31-2512832-M24 & M31-2512893-W03

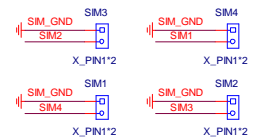
Mounting Holes



Optical Fiducial Marks-120

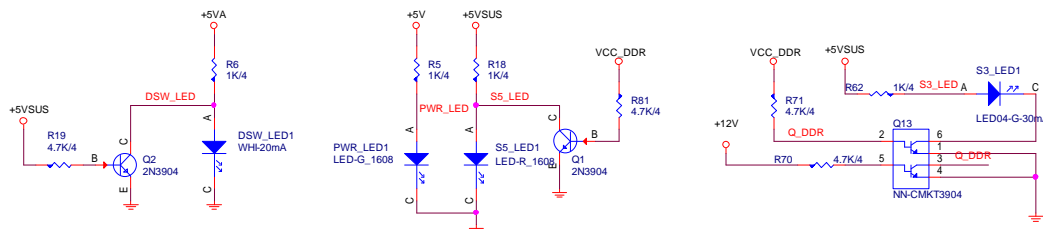


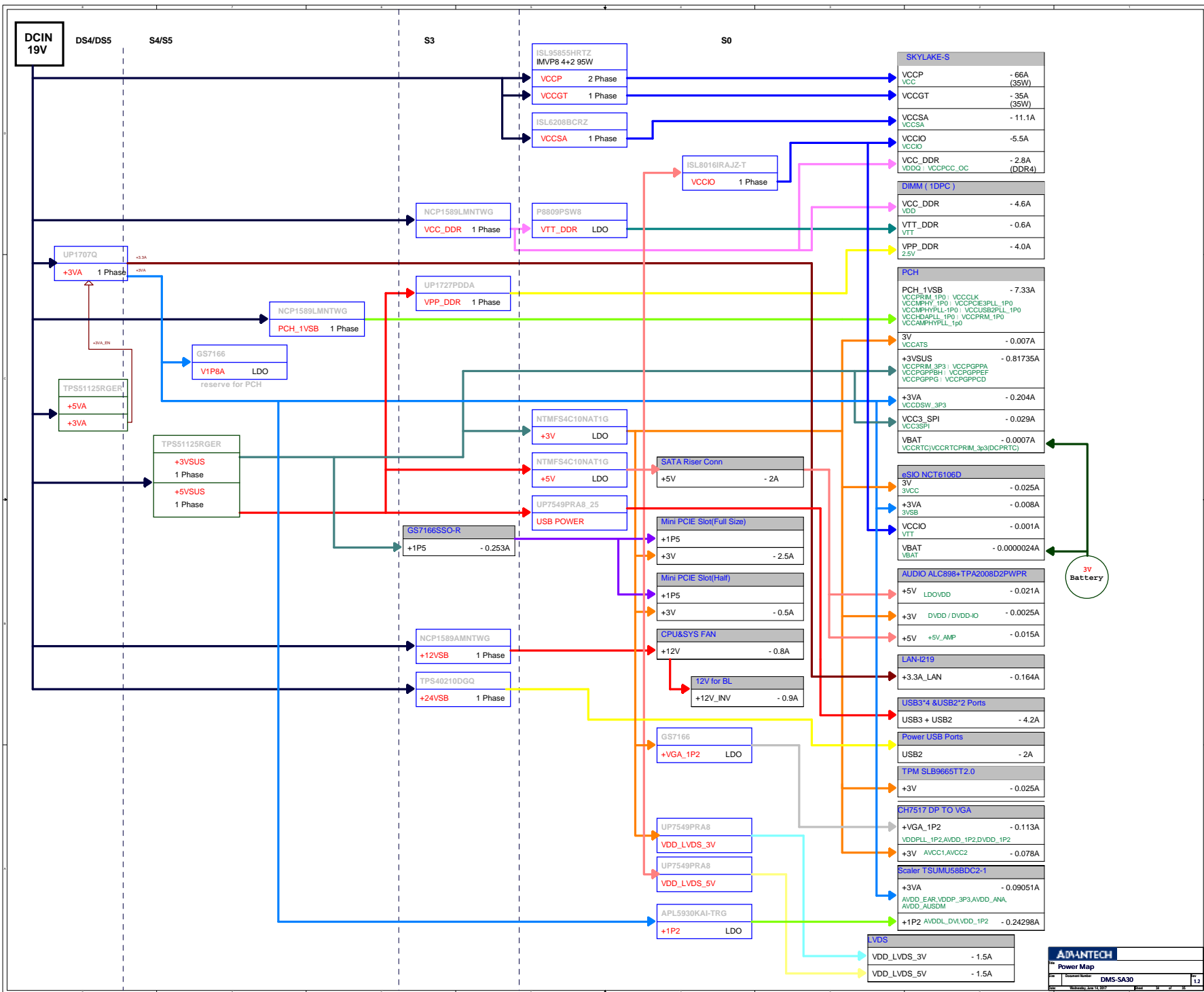
Simulation



Power status LEDs

<Debug only, remove it before MP>





DMS-SA30 Rev.0A : (161226)
DMS-SA30 Rev.0B : (170313)

Page 3:
* The connection of CH7517 (VGA) change from eDP(Port-A) to DP(Port-B) to prevent some limitation of eDP.
Page 5:
* Reserved SLP_S4_CTL from Q59.D1 for the option of turn on timing of +12VSB&+12V.
Page 9:
* Reserve R925 (RST_GL850#) for GL-850 USB HUB.
* Change/Swap configuration of USB2.0 Port 7~14.
* SATA connection change from SATA2B&3B to SATA0B&1B to same as the display of DMS-SA20's BIOS Setup Manual.
Page 10:
* C195 change from 22P50N4 to 12P50N6 and C189 change from 22P50N4 to 15P50N6 by crystal matching test report.
Page 11:
* Change/Swap configuration of USB2.0 OC#3~7.
* No stuff the pull up resistor R391 of PCH_RI# because this function change to SIO by BIOS request.
Page 12:
* C236&C237 change from 12P50N6 to 18P50N6 by crystal matching test report.
* R54 change from 78.7K1%4 to 45.3K1%4 to same as CRB design.
Page 15:
* Y1 change from 14.318M20P(D04-0103000-F07) to 14.318M12P(D04-0103700-F07) by crystal matching test report.
* No stuff D9 and stuff R129 to solve noise from BKL_VBR.(170322)
Page 16:
* C392 change from 10uf6.3X6 to 47u6.3X8 for the inrush current of +5VDD_LVDS.
* C16&C392 stuff 1KR4 to discharge *VDD_LVDS under G3.(170322)
Page 17:
* Add R907~R911 for the gates of Q66~Q70 to prevent gate floating problem.
* Add U55 (GL850 USB2.0 HUB) and related components for H110 SKU.
* Remove RN10~13 ; Add R935~942 for Q170 SKU.
Page 18:
* The connection of CH7517 (VGA) change from eDP (Port-A) to DP (Port-B) to prevent some limitation of eDP.
* F/W version of CH7517 change from 3.1.0.7 (B07-7517A1C-C25) to B000.05.01.13 (B07-7517A4C-C25).
* C298&C298 change from 18P50N4 to 15P50N6 by crystal matching test report.
* Swap D32&D50's connection by layout request.
* L16~L18 change from 82nf300mA to 16nf500mA ; C354/C342/C351/C359/C344/C358 change from 10pf50N4 to 1.5pf50N4 for R/F time and Over/Under shoot adjustment.
Page 19:
* LAN_USB1 change footprint from IOA_RJ45_USB2_LED2_32_1 to IOA_RJ45_USB2_LED2_32.
* C589&C593 change from 22P50N4 to 30P50N6 by crystal matching test report.
* Reserve D52&D53(ESD diode) by EMI request.
Page 20:
* C325&C312 change from 1u16X4 to 0.1u16X4 because Ci must be 10 times smaller than C-Bypass, the value range of C-Bypass is 0.47uf to 1uf.
* C607 change from 1u16X4(X5R) to 1u25X6(X7R) for low-ESR requirement of BYPASS(pin22).
* Change the power source of L36(LDOVDD) from +5V to +5VSUS for S3 wake up noise issue.
* Reserve L41 to add a power source from +5VSUS for +5V_AMP.
Page 21:
* No stuff R10(SERIRQ) because not support TPM card for JTPM1.
Page 22:
* Reserve a connection(SIO_RI#) between U26.45(GP45) and Q83.D by BIOS request.
* Modify Hardware Monitor(Voltage Sense) of +12V change to +19VA and R368 change from 110K1%4 to 180K1%4.
* No stuff Y3&C246 because it only for defensive design.(170322)
Page 23:
* C567&C570 change from 0.1u6.3X4 to 0.047u10X4 ; C568&C588&C587&C571&C591&C592 change from 0.1u6.3X4 to 0.33u6.3X4 to meet the requirement of MAX3243 datasheet.
* Reserve R943&R944 for the signal of RI# by BIOS request.
* Add Q100 and R947 to change the connection from PCH_GPIO to PCH_WAKE# by BIOS request.
Page 24:
* R593 change from 0.01R1%XTRA to 0.02R1%1206 for OCP adjustment.
* FS4 change from RUEF300K to SMD2920P200-24 for safety.
Page 25:
* FS3 change from FUSE-4A to RLD30P300 to same as EXP BD.
Page 26:
* Remove R650 because without current sense feature.
* Reserved R650 (SLP_S4_CTL) for the option of turn on timing of +12VSB&+12V.
* EC22 change from 220uf/16V/Solid DIP (C71-2211610-N07) to 100uf/16V/Solid SMD (C71-1011680-N07) for ME limitation.
* EC21 change from 100uf/16V/EL_DIP (C94-1011621-N07) to 100uf/16V/Solid SMD (C71-1011680-N07) for ME limitation.
* C274 change from 0.047uf10X4 to 0.1uf25X4 & C266 stuff 470pf50X4 & R559 stuff 75R1%4 12V_COMP&FB.
Page 27:
* R51 change from 30K1% to 620K1% to solve +3VA&+5VA abnormal turn on issue.
* The pulled-up PWR source of SUS_ON# change from +3VA to +19VA and R77 change from 10K1% to 140K1% and R69 change from 100K1% to 30K1% to solve +3VSUS&+5VSUS abnormal turn on issue.
Page 28:
* No stuff C475 and C470 change from 0.1uf16X4 to 0.22uf25X6 for ISUM_A.
* C152 change from 0.012uf16X4 to 0.01uf16X4 for ISUM_B.
* R224 change from 93.1KR1% to 88.7KR1% for I-mon.
* R242 change from 1.54K1% to 715R1% to adjust OCP=19A.
* C137 change from 2200pf50X4 to 2700pf50X4 and R245 change from 2.4KR1% to 2.1KR1% for FB_B.
Page 31:
* R800 change from 20KR1% to 5.1KR1% for DDR_COMP.
* Add R926 (10R1%6) and modify circuit to same as the demo circuit of UP1727 (U47)'s datasheet.
Page 33:
* PCB1 change from Rev.0A(P30-07B010A-E48) to Rev.0B(P30-07B010B-E48).
* Remove R651 and change it to CP23(copper) by process request.

Others:
* D20&D37&D38&D42&D43 change from DOG-2950500-SIO to DOG-2710510-I05 by purchase request.
* C190&C216&C464&C468&C469 change from 0.22uf16X4 (C11-2232022-W08) to 0.22uf25X4 (C11-2232022-W08) by purchase request.
* C146 change from 2700pf25X4 (C11-2722022-W08) to 2700pf50X4 (C11-2722822-W08/C11-2722012-S02) by purchase request.
* BIOS_X3 change from W25Q64FVSSIQ (M31-25Q6443-W03) to W25Q64JVSSIQ (M31-25Q64A3-W03) by purchase request.
* All of the net name of PWR_SRC change to +19VA.

DMS-SA30 Rev.10 : (170331)

Page 6:
* Stuff R143&R144&R145 by schematic checklist of XDP.
Page 10:
* DDPD_CTRLDATE pull up to +3V through R949(2.2KR4) to enable DDI Port- B and reserve TP71.
* Add R950 to disable DDI Port-A(eDP).
* R509 change from 10KR4 to 100KR4 for DDPD_HPD3.
Page 12:
* No stuff R551 for TL-624-1.1.
* Add TP72 (PCH_SPL_CS2#) for debug.
Page 16:
* Add discharge resistors R951&R952(1KR4) for +3VDD&+5VDD_LVDS power plane.
* C16&C392 stuff 0.1uf6.3X4.
Page 22:
* No stuff R330 because no SMI# requirement.
Page 23:
* No stuff R947/R854/R846/D47/Q83/Q100 because no need support WOR function. (170410)
Page 29:
* PWRJ1 change from N92-03F0071-F02 to N92-04F0041-S56 by customer request. (170410)
Page 33:
* PCB1 change from Rev.0B(P30-07B010B-E48) to Rev.10(P30-07B0110-E48).

DMS-SA30 Rev.11 : (170508)

Page 10:
* No stuff R513/R411/R498/R826/R437/R507/R516/R464/R485/R454/R442/R465/R500 because un-used related SRCCLK signals.
Page 12:
No stuff SPI-ROM socket on U29 and mount SPI-ROM on U29 directly.
Page 15&17:
* Add a connection (TOUCH_THRU#) from U6.39 to OSD1.30 ; Add Q101/R957/R958/R962 and related circuit by customer request.
Page 18:
* No stuff C622 & C623 to solve the glitch of H/VSYN between 0.5V~2V.
Page 18&23:
* DSUB1 change from N58-24F0251-F02(with screw) to "N59-24M0031-H06"(W/O screw) by customer request.
Page 22:
* No stuff PWRBTN1 because it reserve for debug only.
Page 24:
* Add U56 (TUSB211RWB/R) and related components by customer request.
* No stuff Q96/EC30/C616/C615/C355/R631/R872/Q87/C620 if W/O FS6.
* D48 change from S-PDS560-13(D01-PDS5600-D07) to PMEG060V100EPD(D01-60V100-N78) by purchase request.
Page 27:
* No stuff Q24, it cause Drain Current issue because gate floating.
* Q23 change from 2N7002 to N-3904 ; R105 change from 470KR1% to 140KR1% ; R103 change from 47KR4 to 27KR1% ; R102 change from 178KR1% to 100KR1% and no stuff C82 and R104 for S5 to G3 turn-off timing adjustment.
Page 33:
* R6 change from 680R0603 to 1KR0402 for power saving under DS mode.
* PCB change from Rev.10 to Rev.11.

DMS-SA30 Rev.12 : (170616)

Page 3:
* No stuff R251 because no DP port attached to eDP.
Page 11:
* Add CDW_GPI2(GPP_G7) and pull-up it through R967(10KR) for cash drawer by customer request.
Page 12:
* Add L42/C651/C652/Q102/R964/R965/R966/D55/C650 for CDW_GPI2 by customer request.
Page 19:
* CHoke11 change from L04-47A7210-T36(4.7u1.14A72mS) to L04-47A71B0-L65(4.7u1.14A60mS) by purchase request.
Page 22:
* Stuff PWRBTN1 by QA team request.

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